GR5525 Developer Guide

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Preface

Purpose

This document introduces the Software Development Kit (SDK) of the Goodix GR5525 Bluetooth Low Energy (Bluetooth LE) System-on-Chip (SoC) and Keil for program development and debugging, to help you quickly get started with secondary development of Bluetooth LE applications.

Audience

This document is intended for:

- Device user
- Developer
- Test engineer
- Technical writer

Release Notes

This document is the third release of *GR5525 Developer Guide*, corresponding to GR5525 SoC series.

Revision History

Version	Date	Description
1.0	2023-08-30	Initial release
1.1	2024-03-29	Optimized some descriptions.
1.2	2024-09-02	• Deleted the GR5525IGNI SoC. • Updated the GR5525 SDK directory structure.

Contents

1 Introduction

The Goodix GR5525 series is a single-mode low-power System-on-Chip (SoC) that supports Bluetooth 5.3. It can be configured as a Broadcaster, an Observer, a Central, or a Peripheral, and supports the combination of all the above roles, making it an ideal choice for Internet of Things (IoT) and smart wearable devices.

Based on Arm® Cortex®-M4F CPU core, the GR5525 series integrates Bluetooth 5.3 Protocol Stack, a 2.4 GHz RF transceiver, on-chip programmable Flash memory, RAM, and multiple peripherals.

The GR5525 series comes in two package choices: QFN56 and QFN68 packages. The specific configurations are listed below.

Table 1-1 Configuration of GR5525 series

GR5525 Series	GR5525RGNI	GR5525IENI	GR5525I0NI
CPU	Cortex®-M4F	Cortex®-M4F	Cortex®-M4F
RAM	256 KB	256 KB	256 KB
SiP Flash	1 MB	512 KB	N/A
I/O Number	50	39	39
I/O Voltage	1.8 V–3.6 V	1.8 V–3.6 V	In line with Flash voltage
Package (mm)	QFN68 (7.0 x 7.0 x 0.85)	QFN56 (7.0 x 7.0 x 0.75)	QFN56 (7.0 x 7.0 x 0.75)

1.1 GR5525 SDK

The GR5525 Software Development Kit (SDK) provides comprehensive software development support for GR5525 SoCs. The SDK contains Bluetooth LE APIs, System APIs, peripheral drivers, a tool for debugging and download, project example code, and related user documents.

The GR5525 SDK version mentioned in this document is applicable to all GR5525 SoCs.

1.2 Bluetooth LE Protocol Stack

The Bluetooth LE Protocol Stack (Bluetooth LE Stack) architecture is as shown in the figure below.

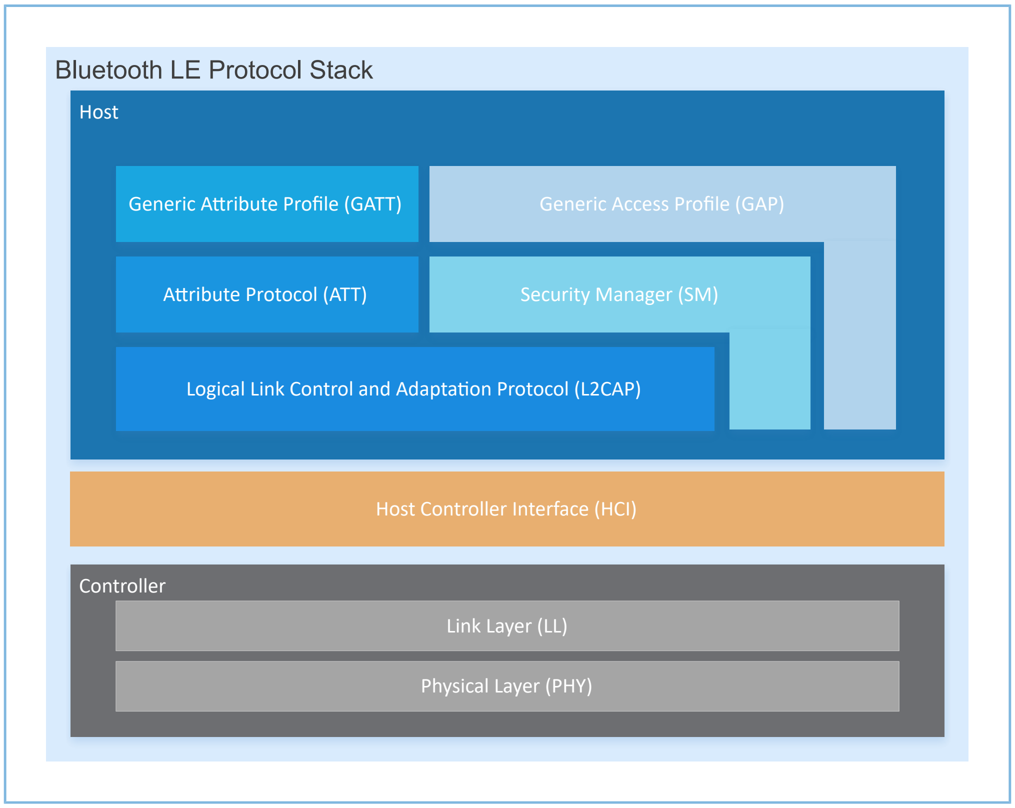

Bluetooth LE Protocol Stack
Host
Generic Attribute Profile (GATT)
Generic Access Profile (GAP)
Attribute Protocol (ATT)
Security Manager (SM)
Logical Link Control and Adaptation Protocol (L2CAP)
Host Controller Interface (HCI)
Controller
Link Layer (LL)
Physical Layer (PHY)

Figure 1-1 Bluetooth LE Stack architecture

The Bluetooth LE Stack consists of the Controller, the Host Controller Interface (HCI), and the Host.

Controller

- Physical Layer (PHY): Supports 1-Mbps and 2-Mbps adaptive frequency hopping and Gaussian Frequency Shift Keying (GFSK).
- Link Layer (LL): Controls the RF state of devices. Devices are in one of the following five states, and can switch between the states on demand: Standby, Advertising, Scanning, Initiating, and Connection.

HCI

- HCI: Enables communication between Host and Controller, supported by software interfaces or standard hardware interfaces; for example, UART, Secure Digital (SD), or USB. HCI commands and events are transferred between Host and Controller through HCI.

Host

- Logical Link Control and Adaptation Protocol (L2CAP): Provides channel multiplexing and data segmentation and reassembly services for upper layers. It also supports logic end-to-end data communication.
- Security Manager (SM): Defines pairing and key distribution methods, providing upper-layer protocol stacks and applications with end-to-end secure connection and data exchange functionalities.
- Generic Access Profile (GAP): Provides upper-layer applications and profiles with interfaces to communicate and interact with protocol stacks, fulfilling functionalities such as advertising, scanning, connection initiation, service discovery, connection parameter update, secure process initiation, and response.

- Attribute Protocol (ATT): Defines service data interaction protocols between a server and a client.
- Generic Attribute Profile (GATT): Based on the top of ATT, it defines a series of communication procedures for upper-layer applications, profiles, and services to exchange service data between GATT Client and GATT Server.

Tip:

For more information about Bluetooth LE technologies and protocols, visit the Bluetooth SIG official website: https://www.bluetooth.com.

Specifications of GAP, SM, L2CAP, and GATT are provided in *Bluetooth Core Spec*. Specifications of other profiles/services at the Bluetooth LE application layer are available on the GATT Specs page. Assigned numbers, IDs, and code which may be used by Bluetooth LE applications are listed on the Assigned Numbers page.

2 GR5525 Bluetooth LE Software Platform

The GR5525 SDK is designed for GR5525 SoCs, to help users develop Bluetooth LE applications. It integrates Bluetooth LE 5.3 APIs, System APIs, and peripheral driver APIs, with various example projects and instruction documents for Bluetooth and peripheral applications. Application developers are able to quickly develop and iterate products based on example projects in the GR5525 SDK.

2.1 Hardware Architecture

The GR5525 hardware architecture is shown as follows.

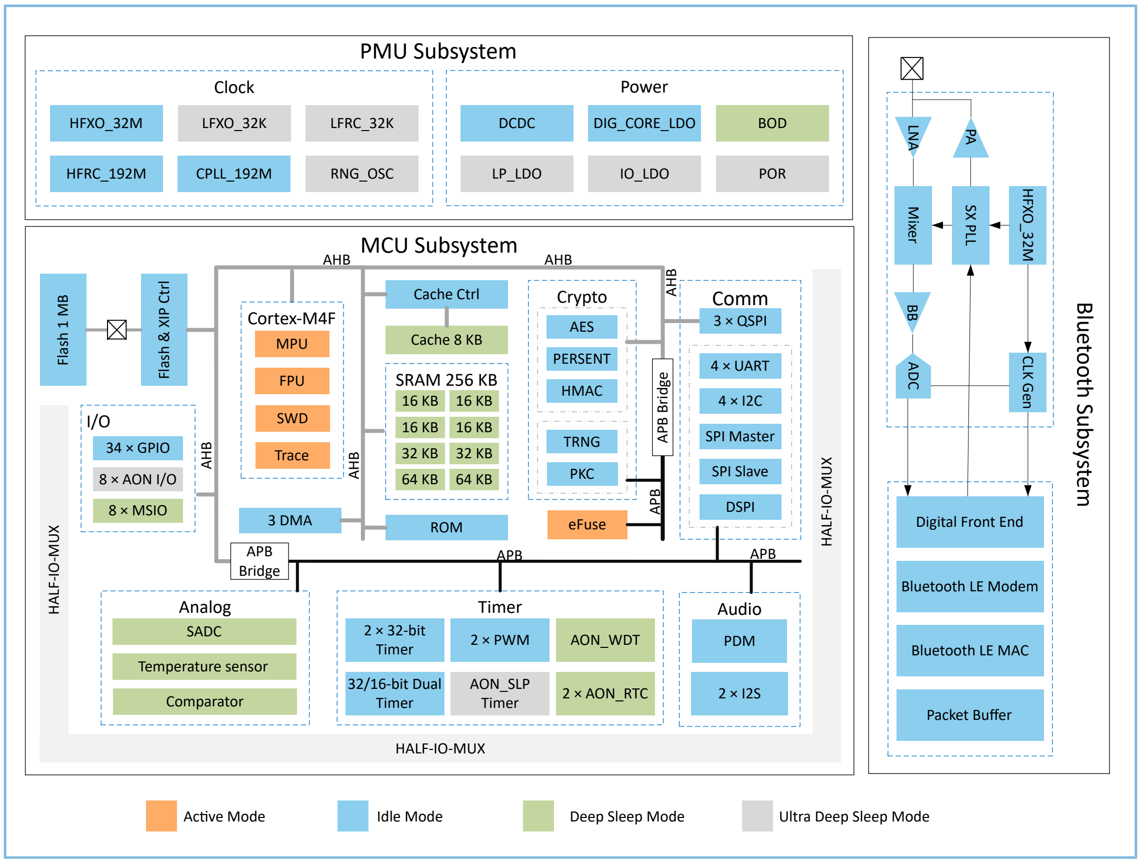


Figure 2-1 GR5525 hardware architecture

- Bluetooth subsystem:
  - Include a 2.4 GHz RF transceiver and a digital communication controller, both supporting Bluetooth LE 5.3.
- MCU subsystem:
  - Include an Arm® Cortex®-M4F CPU core, memories, and peripherals.
  - Security modules supports security application and secure boot implementation.
- Power Management Unit (PMU) subsystem:
  - Power supply for the whole SoC, including internal modules and peripherals

- Support ultra deep sleep mode in standby state and control the power state of the system or peripherals by HFRC_192M, RNG_OSC, LFRC_32K, wake-up GPIOs (Wake-up), low-power comparator (LP Comp.) and power state controller (Power Sequencer).

Tip:

For more details about GR5525 modules, refer to *GR5525 Datasheet*.

2.2 Software Architecture

The software architecture of GR5525 SDK is shown below.

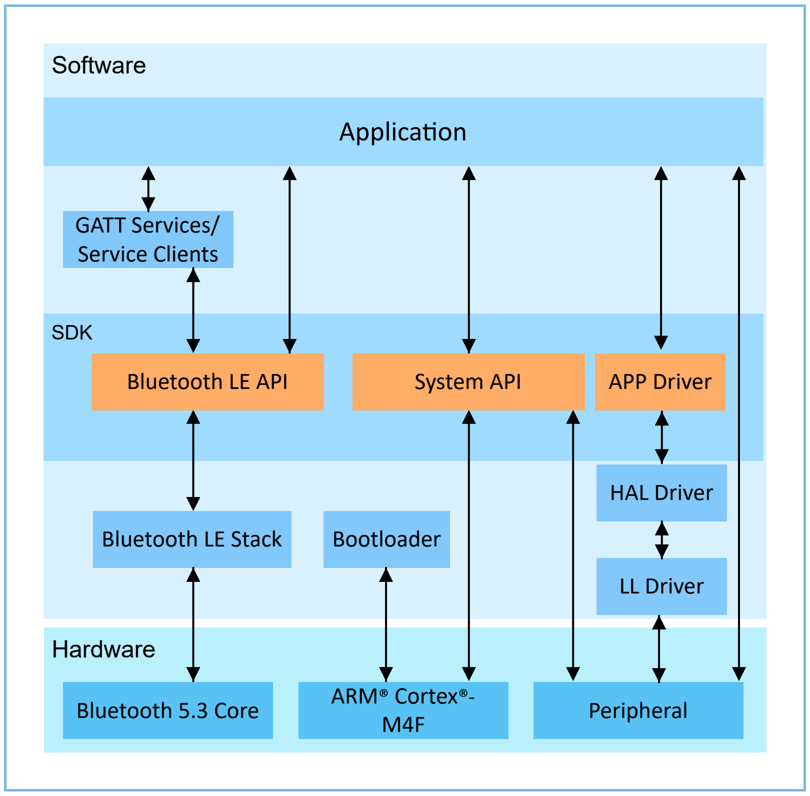


Figure 2-2 GR5525 software architecture

- Bootloader

  A boot program built in GR5525 SoCs, used for GR5525 software and hardware environment initialization, and to check and start applications

- Bluetooth LE Stack

  The core to implement Bluetooth LE protocols. It consists of Controller, HCI, and Host protocols (including ATT, L2CAP, GAP, SM, and GATT), and supports roles of Broadcaster, Observer, Peripheral, and Central.

- HAL Driver

  Hardware Abstraction Layer (HAL) drivers; the HAL Driver layer is between the APP Driver layer and the LL Driver layer. HAL drivers offer a set of standard APIs, to allow the APP Driver layer to access the LL peripheral resources by calling HAL APIs.

Note:

Generally, HAL APIs are used for developing LL drivers and system services, not for developing common applications. Therefore, it is not recommended for developers to directly call HAL APIs.

- LL Driver

  Low Layer (LL) drivers which control and manage peripherals by registers

- Bluetooth LE SDK

  SDK that provides easy-to-use Bluetooth LE APIs, system APIs, and APP driver APIs.

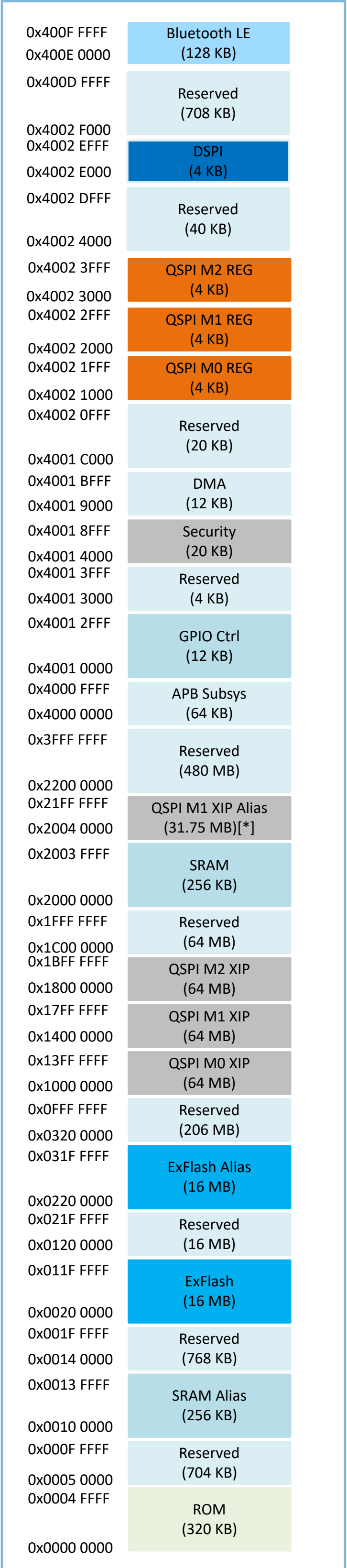
  - Bluetooth LE APIs: Includes L2CAP, GAP, SM, and GATT APIs.
  - System APIs: Provides APIs for Non-volatile Data Storage (NVDS), Device Firmware Update (DFU), system power management, and generic system-level access.
  - APP driver APIs: Provides definitions for APIs of common peripherals such as UART, I2C, and ADC. APP driver APIs call HAL/LL APIs to enable the corresponding functionalities.

- Application

  The SDK provides abundant Bluetooth and peripheral example projects. Each project contains compiled binary files; you can download these files to GR5525 SoCs for operation and test. GRToolbox (Android) in the SDK provides rich functionalities to allow users to test most Bluetooth applications with ease.

2.3 Memory Mapping

The memory mapping of a GR5525 SoC is shown below.



Note:
[*] Only a part of XIP range can be accessed.

Figure 2-3 GR5525 memory mapping

- RAM: 0x0010_0000 to 0x0013_FFFF, or 0x2000_0000 to 0x2003_FFFF; 256 KB in total
    - 0x2000_0000 to 0x2003_FFFF: bit field operations supported, mapping to the region from 0x2200_0000 to 0x227F_FFFF, in which atomic operations are supported. Variables of the SDK including RW, ZI, HEAP, and STACK are in this range.
    - 0x0010_0000 to 0x0013_FFFF: This region features higher access efficiency thanks to the Cortex®-M4F architecture. Therefore, RAM_CODE is in this area.

Note:

QSPI0, QSPI1, and QSPI2 support the Execute in Place (XIP) mode, which allows mapping of address from QSPI Flash to memories, enabling direct operations on memories.

- Flash: 0x0020_0000 to 0x011F_FFFF or 0x0220_0000 to 0x031F_FFFF, 16 MB in total
    - 0x0020_0000 to 0x011F_FFFF: Stores code and unencrypted data.
    - 0x0220_0000 to 0x031F_FFFF: Stores encrypted data.

Note:

Internal Flash of GR5525 SoCs is 1 MB, from 0x0020_0000 to 0x002F_FFFF.

2.4 Flash Memory Mapping

GR5525 packages an external erasable Flash memory, which supports XQSPI bus interface. This Flash memory physically consists of several 4 KB Flash sectors; it can be logically divided into storage areas for different purposes based on application scenarios.

The Flash memory layout for typical GR5525 application scenarios is shown below.

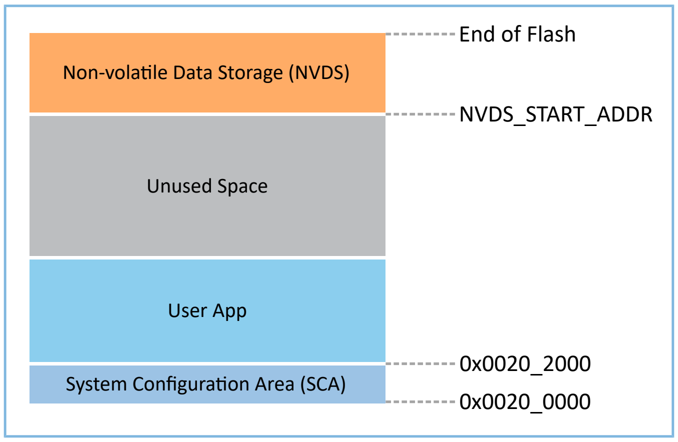


Figure 2-4 Flash memory layout

- System Configuration Area (SCA): an area to store configurations such as system boot parameters
- User App: an area to store application firmware

- Unused Space: a free area for developers. For example, developers can store new application firmware in the Unused Space temporarily during DFU.
- NVDS: non-volatile data storage area

Note:

By default, NVDS occupies the last two sectors of Flash memory. You can configure the start address of NVDS and the number of occupied sectors according to Flash memory layout of products. For more information about the configuration, refer to "Section 4.3.2.1 Configuring custom_config.h".

The start address of NVDS shall be aligned with that of the Flash sectors.

2.4.1 SCA

SCA is in the first two sectors (8 KB in total; 0x0020_0000 to 0x0020_2000) of Flash memory. It mainly stores flags and other system configuration parameters used during system boot.

During firmware download, the download algorithm or GProgrammer will generate Image Info based on the BUILD_IN_APP_INFO structure in the application firmware, and program the Image Info (stored in SCA) to Flash along with the application firmware. During system boot, Bootloader will check the boot information in SCA, and then jump to the entry address of the firmware if the check passes.

The BUILD_IN_APP_INFO structure is defined and configured as follows:

Tip:

The BUILD_IN_APP_INFO structure is in `SDK_Folder\platform\soc\common\gr_platform.c`, and SDK_Folder is the root directory of GR5525 SDK.

```
const APP_INFO_t BUILD_IN_APP_INFO __attribute__((section(".app_info"))) =
#endif
{
    .app_pattern      = APP_INFO_PATTERN_VALUE,
    .app_info_version = APP_INFO_VERSION,
    .chip_ver         = CHIP_VER,
    .load_addr        = APP_CODE_LOAD_ADDR,
    .run_addr         = APP_CODE_RUN_ADDR,
    .app_info_sum     = CHECK_SUM,
    .check_img        = BOOT_CHECK_IMAGE,
    .boot_delay       = BOOT_LONG_TIME,
    .sec_cfg          = SECURITY_CFG_VAL,
#ifdef APP_INFO_COMMENTS
    .comments         = APP_INFO_COMMENTS,
#endif
};
```

- app_pattern: a fixed value 0x47525858
- app_info_version: firmware version information, corresponding to APP_INFO_VERSION
- chip_ver: version of the SoC that the firmware runs on, corresponding to CHIP_VER in *custom_config.h*
- load_addr: firmware load address, corresponding to APP_CODE_LOAD_ADDR in *custom_config.h*

- run_addr: firmware run address, corresponding to APP_CODE_RUN_ADDR in *custom_config.h*
- app_info_sum: checksum of firmware information, which is automatically calculated by CHECK_SUM
- check_img: system boot configuration parameter, corresponding to BOOT_CHECK_IMAGE in *custom_config.h*. When check_img is set to 1, Bootloader will check the firmware at booting.
- boot_delay: boot configuration parameter, corresponding to BOOT_LONG_TIME in *custom_config.h*. When boot_delay is set to 1, the system cold boot will be launched after a one-second delay.
- sec_cfg: security configuration parameter, reserved
- comments: firmware information, up to 12 bytes

The SCA layout is shown below.

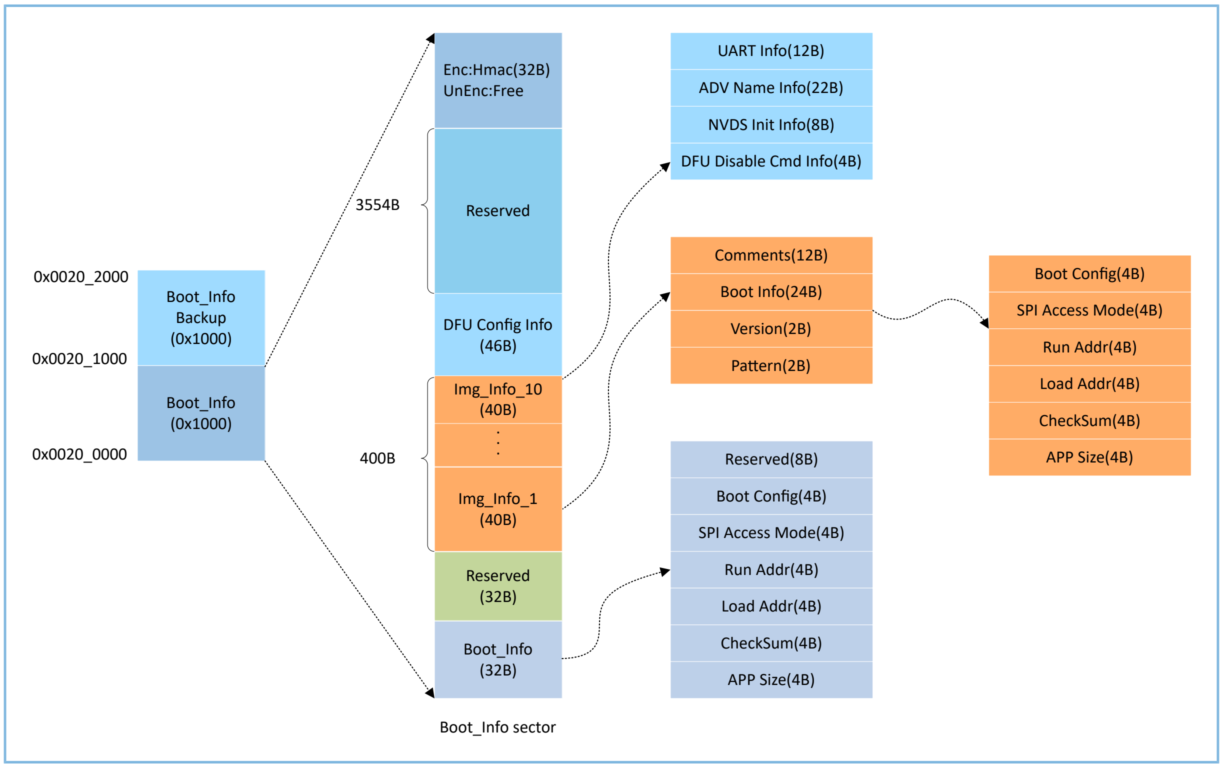


Figure 2-5 SCA layout

- Boot_Info and Boot_Info Backup store the same information. The latter is the backup of the Boot_Info.
  - In non-security mode, the Bootloader obtains boot information from Boot_Info by default.
  - In security mode, the Bootloader checks Boot_Info first; if the check fails, the Bootloader checks Boot_Info Backup and obtains boot information from it.
- The firmware boot information is stored in the Boot_Info (32 B) area. During system boot, Bootloader will check the boot information, and then jump to the entry address of the firmware if the check passes.
  - Boot Config: This area stores the system boot configuration information.

    - SPI Access Mode: This area stores the SPI access mode configuration. It is a fixed configuration of the system and cannot be modified.
    - Run Addr: Indicates the firmware run address, corresponding to run_addr of BUILD_IN_APP_INFO.
    - Load Addr: Indicates the firmware load address, corresponding to load_addr of BUILD_IN_APP_INFO.
    - CheckSum: This area stores the firmware checksum which is calculated automatically by the download algorithm after firmware is generated.
    - APP Size: This area stores the firmware size which is calculated automatically by the download algorithm after firmware is generated.
- Up to 10 pieces of firmware information can be stored in Img_Info areas. Firmware information is stored in Img_Info areas when you use GProgrammer to download firmware or update firmware in DFU mode.
    - Comments: This area stores the descriptive information (up to 12 characters) about firmware. Every time a firmware file is generated, the file name will be saved in the Comments area by the download algorithm.
    - Boot Info (24 B): This area stores the firmware boot information which is the same as the low 24-byte information in the Boot_Info (32 B) area mentioned above.
    - Version: This area stores the firmware version, corresponding to VERSION in the *custom_config.h*.
    - Pattern: This area stores a fixed value 0x4744.
- The DFU Config Info area stores configurations of DFU module in ROM#
    - UART Info: This area stores UART configurations of DFU module, including state bit, baud rate, and GPIO configurations.
    - ADV Name Info: This area stores advertising configurations of DFU module, including state bit, advertising name, and advertising length.
    - NVDS Init Info: This area stores initialization configurations of NVDS system in DFU module, including state bit, NVDS area size, and start address.
    - DFU Disable Cmd Info: This area stores DFU disable command configurations of DFU module, including state bit and Disable DFU Cmd (2 B, set as Bitmask). You can set the Disable DFU Cmd value to disable a DFU command.
- The HMAC area stores the HMAC check value. This area is valid only in security mode.

2.4.2 NVDS

NVDS is a lightweight logical data storage system based on Flash HAL. NVDS is located in the Flash memory and data in it will not get lost in power-off state. By default, NVDS uses the last two sectors of the Flash memory. You can also configure the number of Flash sectors to be occupied. In NVDS, the last sector is for defragmentation, and the other sector(s) for data storage.

NVDS is an ideal choice to store small data blocks, for example, application configuration parameters, calibration data, states, and user information. Bluetooth LE Stack stores parameters such as device binding parameters in NVDS.

NVDS features:

- Each storage item (TAG) has a unique TAG ID. User applications can read and change data according to TAG IDs, regardless of physical storage addresses.
- It is optimized based on medium characteristics of Flash memory and supports data check, word alignment, defragmentation, and erase/write balance.
- The size and start address of NVDS are configurable. Compared with Flash memory which is made up of 4 KB sectors, NVDS can be in several sectors as configured. Make sure the start address of NVDS is 4 KB aligned.

Note:

- You can configure the start address and size of the NVDS area by adding the NVDS_START_ADDR macro and modifying the NVDS_NUM_SECTOR macro respectively in *custom_config.h*.
- Bluetooth LE Stack and the application share the same NVDS storage area. However, TAG ID namespace is divided into different categories. You can only use the TAG ID name category assigned to an application.
    - Applications have to use NV_TAG_APP(idx) to obtain the TAG ID of application data. The TAG ID is used as an NVDS API parameter.
    - Applications cannot use idx as the NVDS API parameter directly. The idx value ranges from 0x4000 to 0x7FFF.
- Before running an application for the first time, you can use GProgrammer to write the initial TAG ID value used by Bluetooth LE Stack and the application to NVDS.
- If you specify an NVDS area, instead of using the default NVDS area in the GR5525 SDK, make sure the start address of the NVDS area configured in GProgrammer is 4 KB aligned.

Data stored in NVDS is in the format below.

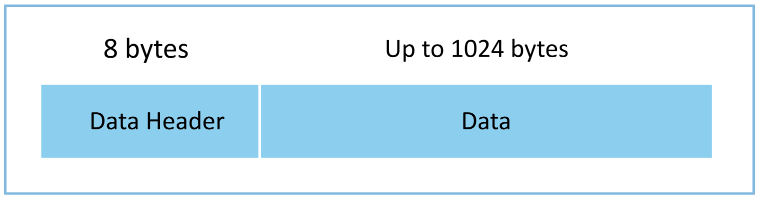


Figure 2-6 Data format in NVDS

Details of data header are described below.

Table 2-1 Data header format

Byte	Name	Description
0–1	tag	Data tag
2–3	len	Data length
4–4	checksum	Checksum of data header
5–5	value_cs	Checksum of data

Byte	Name	Description
6–7	reserved	Reserved bits

GR5525 SDK provides the following NVDS APIs to allow developers to manipulate non-volatile data in Flash.

Table 2-2 NVDS APIs

Function Prototype	Description
uint8_t nvds_init(uint32_t start_addr, uint8_t sectors)	Initialize the Flash sectors used by NVDS.
uint8_t nvds_get(NvdsTag_t tag, uint16_t *p_len, uint8_t *p_buf)	Read data according to TAG IDs from NVDS.
uint8_t nvds_put(NvdsTag_t tag, uint16_t len, const uint8_t *p_buf)	Write data to NVDS and mark the data with TAG IDs. You need to create a TAG ID when writing data for the first time.
uint8_t nvds_del(NvdsTag_t tag)	Remove the corresponding data of a TAG ID in NVDS.
uint16_t nvds_tag_length(NvdsTag_t tag)	Obtain the data length of a specified TAG ID.
uint8_t nvds_drv_func_replace(nvds_drv_func_t *p_nvds_drv_func)	Replace the APIs that can directly control Flash.
uint8_t nvds_func_replace(nvds_func_t *p_nvds_func)	Replace the APIs that control NVDS.
void nvds_retention_size(uint8_t bond_dev_num)	Reserve space for device bonding. The space reserved depends on the number of devices to be bonded.

Note:

For details of NVDS APIs, refer to the NVDS header file (in `SDK_Folder\components\sdk\gr55xx_nvds.h`).

2.5 RAM Mapping

The RAM of a GR5525 SoC is 256 KB in size with the start address of 0x2000_0000. It consists of eight RAM blocks. Each of the first four RAM blocks is 16 KB, followed by two 32 KB blocks, and two 64 KB blocks in sequence. Each RAM block can be powered on or off by software independently.

Note:

GR5525 provides RAM (start address: 0x2000_0000) with an aliasing memory (start address: 0x0010_0000). For more information, see Figure 2-3.

- The region (start address: 0x2000_0000) supports bit field operations, mapping to the region starting from 0x2200_0000.
- The region starting from 0x0010_0000 features higher access efficiency thanks to the Cortex®-M4F architecture. Therefore, executing code in this region promotes running speed.
- In the GR5525 SDK, RW, ZI, HEAP, and STACK use the RAM region starting from 0x2000_0000; RAM_CODE uses the region starting from 0x0010_0000.

The 256 KB RAM layout is shown below.

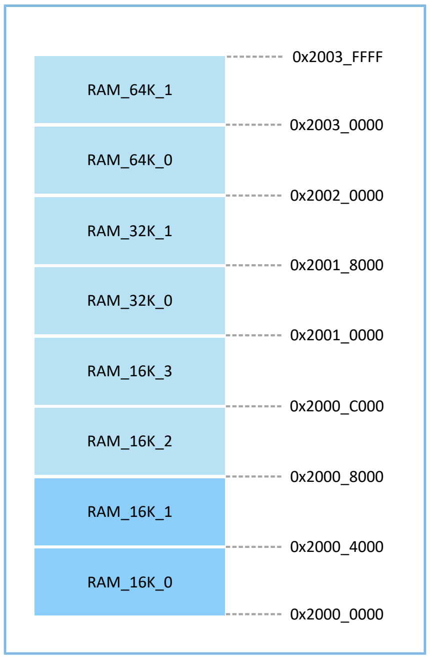


Figure 2-7 256 KB RAM layout

Running modes for applications include XIP and mirror modes. For more information about configurations, see **APP_CODE_RUN_ADDR** in "Section 4.3.2.1 Configuring custom_config.h". RAM layouts of the two modes are different.

Table 2-3 Running modes for applications

Running Mode	Description
XIP mode	It refers to Execute in Place mode. User applications are stored in on-chip Flash, and applications use the same space for running and loading. When the system is powered on, it fetches and executes commands from Flash directly through the Cache Controller.
Mirror mode	In mirror mode, user applications are stored in on-chip Flash, and the running space for applications is defined in RAM. During application boot, applications are loaded into RAM from external Flash after check is completed, and the system jumps to RAM for operation.

Note:

Continuous access to Flash is required in XIP mode. Therefore, power consumption in this mode is a little higher than that in mirror mode.

2.5.1 Typical RAM Layout in XIP Mode

The typical RAM layout in XIP mode is shown below. Users can modify the layout based on product needs.

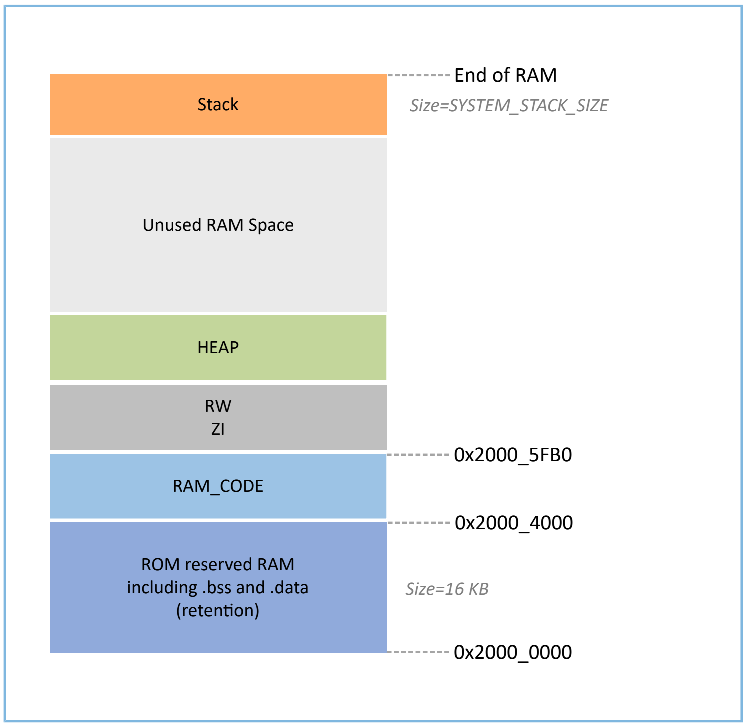


Figure 2-8 RAM layout in XIP mode

RAM_CODE saves code executed in RAM. To boost the efficiency in execution, it is recommended to define this region in the aliasing memory (at physical address 0x0010_0000).

The layout in XIP mode allows application firmware to be run directly in the code loading area, so that more RAM space is available for applications. During update to contents in Flash memory, XIP mode is disabled; during erase/ write operations with the smallest granularity (256 bytes for writing and 4 KB for erasing), interrupts cannot be generated.

Note:

- QSPI0, QSPI1, and QSPI2 support the XIP mode, which allows mapping of address from QSPI Flash to memories, enabling direct operations on memories.
- Users can add self-defined sections as needed. Avoid modifying the default scatter file of the SDK or deleting part of the scatter file (such as deleting **RAM_CODE** from the scatter file). For details about the scatter file, see "Section 4.3.2.2 Configuring Memory Layout".

2.5.2 Typical RAM Layout in Mirror Mode

The typical RAM layout in mirror mode is shown below. Users can modify the layout based on product needs.

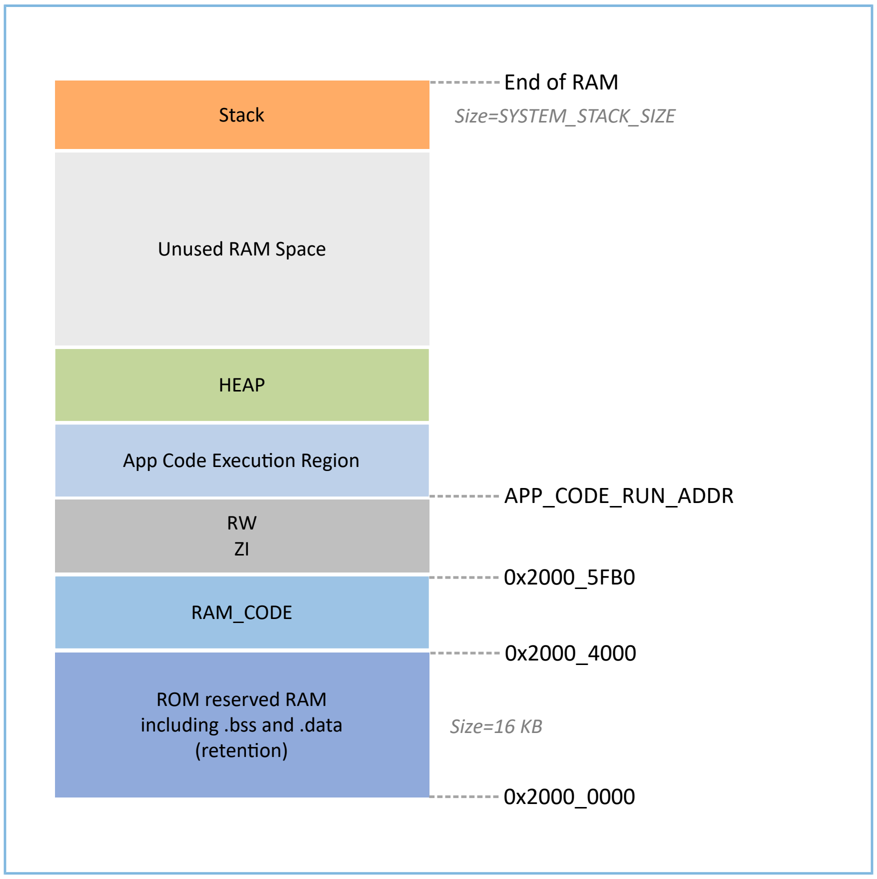


Figure 2-9 RAM layout in mirror mode

The layout in mirror mode allows application firmware to be run in RAM. The SoC enters cold boot process after power-on. The Bootloader copies application firmware from flash to the RAM segment **App Code Execution Region**. After wake-up from sleep mode, GR5525 SoC enters warm boot process. To shorten the warm boot time, the Bootloader does not redo copy of application firmware to the RAM segment **App Code Execution Region**.

The start address of the **App Code Execution Region** segment depends on APP_CODE_RUN_ADDR in *custom_config.h*. Users need to decide the value of APP_CODE_RUN_ADDR based on the use of .data and .bss segments, to avoid overlapping with the .bss segment at lower address or the Call Stack segment at higher address. Users can view the layout of RAM segments from the *.map* file.

It is recommended to set APP_CODE_RUN_ADDR with RAM Aliasing Memory address (from 0x0010_0000 to 0x0013_FFFF). Once overlapping with RAM segments happens, when a project is to be built, an error will occur and the overlapped part will be indicated, to help users quickly check and locate the overlapped part in the RAM.

2.5.3 RAM Power Management

Each RAM block has three power modes: Full Power, Retention Power, and Power Off.

- Full Power: The system is in active state; MCU is permitted to read from and write to RAM blocks.
- Retention Power: The system is in sleep state; data in RAM blocks does not get lost and is ready for use by the system when it switches from sleep state to active state.

- Power Off: The system is in power-off state; RAM blocks will be powered off and the data in the blocks will get lost. Therefore, you need to save the data before the system is powered off.

By default, the PMU in the GR5525 enables all RAM power sources when the system starts. The GR5525 SDK also provides a complete set of RAM power management APIs. You can configure the power state of RAM blocks based on application needs.

By default, the system enables automatic RAM power management mode during boot: It automatically implements power mode control of RAM blocks according to RAM usage of applications. The configuration rules are provided as follows:

- When the system is in active state, set the unused RAM blocks to **Power Off** mode, and RAM blocks to be used to **Full Power** mode.
- When the system is in sleep state, set the unused RAM blocks to **Power Off** mode, and RAM blocks to be used to **Retention Power** mode.

Recommended RAM configurations in practice are described below:

- In Bluetooth LE applications, the first 8 KB of RAM_16K_0 and RAM_16K_1 are reserved for Bootloader and Bluetooth LE Stack only, not available for applications. When the system is in active state, RAM_16K_0 and RAM_16K_1 shall be in **Full Power** mode; when the system is in sleep state, the two RAM blocks shall be in **Retention Power** mode. Non-Bluetooth LE MCU applications can use these two RAM blocks.
- Purposes of RAM_16K_2 and subsequent RAM blocks are defined by applications. Generally, user data and the code segments to be executed in RAM are defined in continuous segments starting from RAM_16K_2; the top of function call stacks is defined in upper address part of RAM. The power mode of these RAM blocks can be enabled, or be controlled by applications.

Note:

- An MCU access is permitted only when a RAM block is in **Full Power** mode.
- Details about RAM power management APIs are in `SDK_Folder\components\sdk\platform_sdk.h`.

2.6 SDK Directory Structure

The folder directory structure of GR5525 SDK is shown as follows.

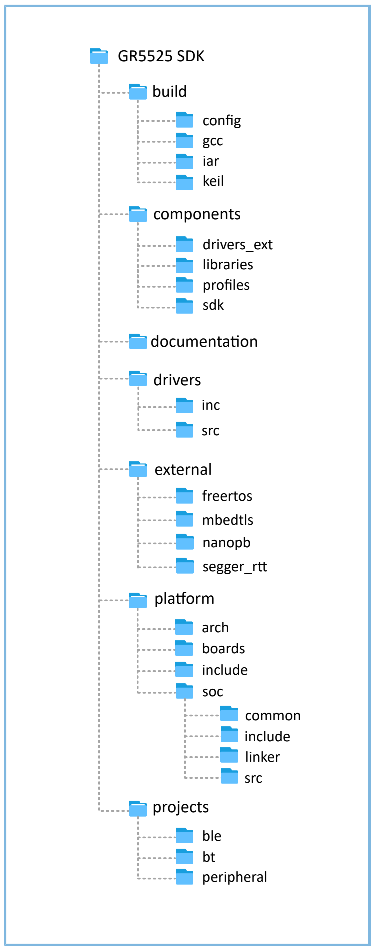


Figure 2-10 GR5525 SDK directory structure

Detailed description of folders in the GR5525 SDK is shown below.

Table 2-4 GR5525 SDK folders

Folder	**Description**
build\config	Project configuration directory that stores the *custom_config.h* template file. This file is used to configure projects and parameters.
build\gcc	GCC tools
build\keil	Keil MDK tools
build\iar	IAR tools
components\drivers_ext	Drivers of third-party components on the development board
components\libraries	Libraries provided in the GR5525 SDK
components\profiles	Source files of GATT Services/Service Clients implementation examples provided in the GR5525 SDK
components\sdk	API header files provided in the GR5525 SDK
documentation	*GR5525 API Reference Manual*

Folder	Description
drivers\inc	Driver API header files which are easy to use for application developers
drivers\src	Driver API source code which is easy to use for application developers
external\freertos	Source code of FreeRTOS (a third-party program)
external\mbedtls	Source code of Mbed TLS (a third-party program)
external\nanopb	Source code of Nanopb (a third-party program)
external\segger_rtt	Source code of SEGGER RTT (a third-party program)
platform\arch	Toolchain files of CMSIS
platform\boards	Source files for initializing GR5525 Starter Kit Board. The files are used for initializing basic peripherals at board level.
platform\include	Common header files related to platform
platform\soc\common	Public source files compatible to GR5525 SoCs. The files include *gr_interrupt.c*, *gr_platform.c*, and *gr_system.c*.
platform\soc\linker	Symbol table files and library files for the linker
platform\soc\include	Common header files closely related to underlying driver configurations such as registers and clock configurations
platform\soc\src	*gr_soc.c* which is about initialization processes closely related to SoC implementation. The processes include initializing Flash and NVDS, configuring crystal, and calibrating PMU.
projects\ble	Bluetooth LE application project examples, such as Heart Rate Sensor and Proximity Reporter
projects\bt	BT example project
projects\peripheral	Peripheral project examples of a GR5525 SoC

3 Bootloader

The GR5525 supports two firmware running modes: XIP and mirror. When the system is powered on, the Bootloader first reads the system boot configuration information from SCA, then performs application firmware integrity check and initialization configuration accordingly, and finally jumps to the code running space to run firmware. The boot procedures may vary in different running modes.

- In XIP mode, the Bootloader first initializes Cache and XIP controllers after finishing application firmware check, and then jumps to the code run address in Flash to run code.
- In mirror mode, after finishing application firmware check, the Bootloader loads the firmware in Flash to corresponding RAM running space based on system configurations, and jumps to and runs the firmware in RAM.

The application boot procedures of the GR5525 SDK are shown as follows.

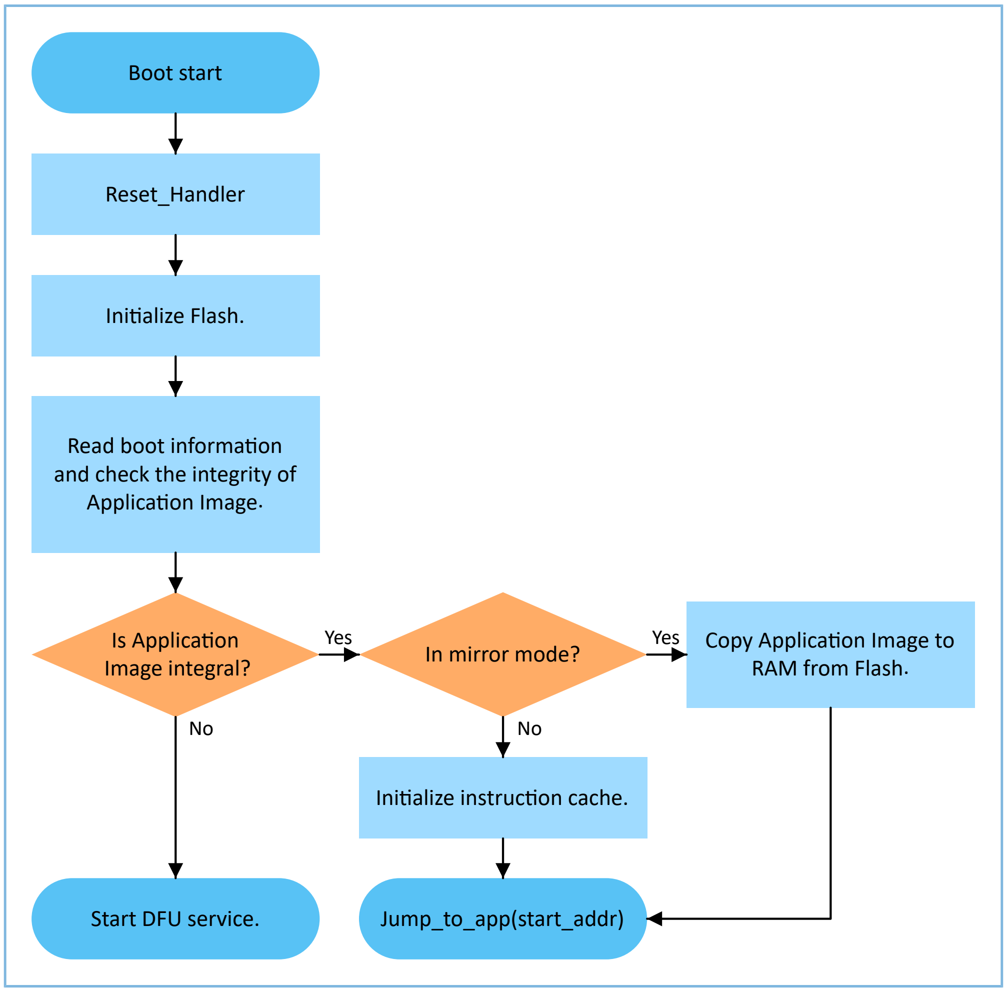

Boot start
Reset_Handler
Initialize Flash.
Read boot information and check the integrity of Application Image.
Is Application Image integral?
Yes
No
In mirror mode?
Yes
No
Copy Application Image to RAM from Flash.
Initialize instruction cache.
Start DFU service.
Jump_to_app(start_addr)

Figure 3-1 Application boot procedures of the GR5525 SDK

1. When the device is powered on, CPU jumps to 0x0000_0000 to extract the extended stack pointer (ESP) of C-Stack and assigns the value to the main stack pointer (MSP). Then, the program counter (PC) jumps to 0x0000_004, and executes Reset_Handler in ROM to enter the Bootloader.
2. Bootloader initializes Flash.

3. Bootloader reads boot information from SCA in Flash and checks application firmware integrity.

Note:

GR5525 supports encrypting and signing application firmware in security mode.

- Security mode: If the security mode is enabled, the Bootloader reads boot information from SCA and performs HMAC check; after the check succeeds, the Bootloader decrypts SCA boot information and then implements the signature verification process in the secure boot process, to guarantee firmware integrity and prevent tampering or disguise; if signature verification succeeds, the automatic decryption functionality is enabled.
- Non-security mode: If the security mode is not enabled, the Bootloader performs cyclic redundancy check (CRC) on application firmware based on SCA boot information.

---

4. If the integrity check fails, the Bootloader starts the Bluetooth LE DFU service.
5. If the integrity check succeeds, the Bootloader checks the running mode.
    - In XIP mode, the Bootloader jumps to the application firmware in Flash to start implementation after XIP configuration is completed.
    - In mirror mode, the Bootloader copies the application firmware in Flash to a specified segment in RAM, and then runs the application firmware in RAM.

4 Development and Debugging with GR5525 SDK in Keil

This chapter introduces how to build, compile, download, and debug Bluetooth LE applications with the GR5525 SDK in Keil.

4.1 Installing Keil MDK

Keil MDK-ARM IDE (Keil) is an Integrated Development Environment (IDE) provided by Arm® for Cortex® and Arm devices. You can download and install the Keil installation package from the Keil official website: https://www.keil.com/demo/eval/arm.htm. For the GR5525 SDK, Keil V5.20 or a later version shall be installed.

Note:

For more information about how to use Keil MDK-ARM IDE, refer to online manuals provided by ARM®: https://www.keil.com/support/man_arm.htm.

The main interface of Keil is as shown below.

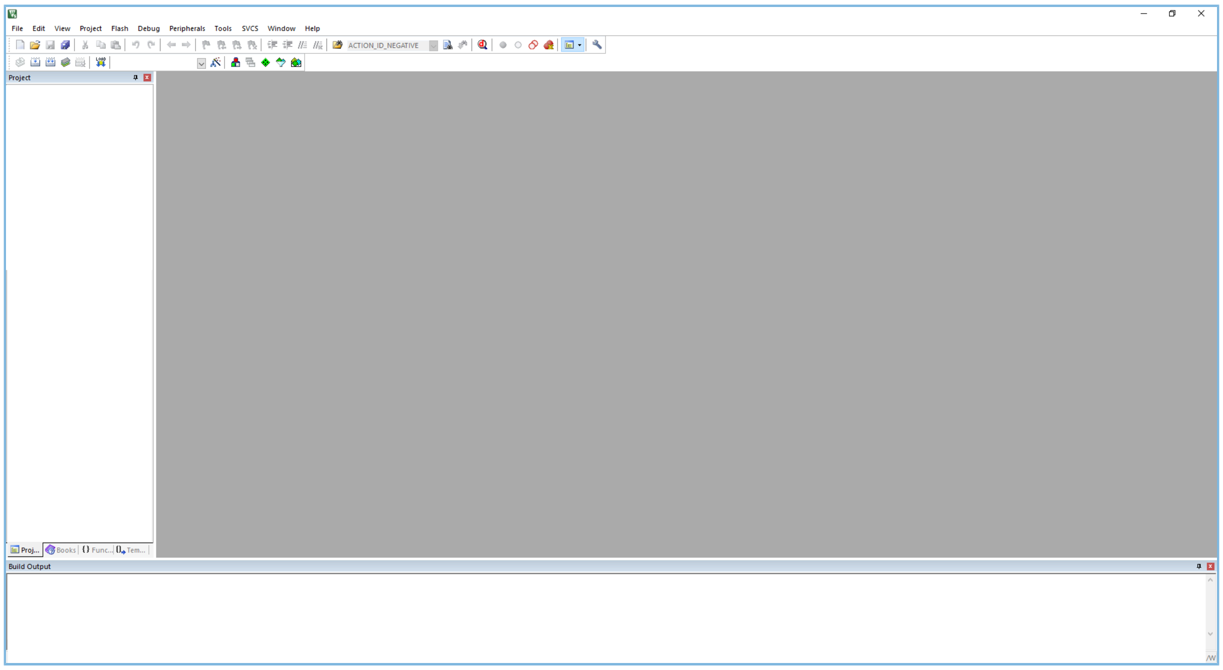


Figure 4-1 Keil interface

Frequently used function buttons of Keil are listed below:

Table 4-1 Frequently used function buttons of Keil

Button	Description
🔧	Options for Target
🔍	Start/Stop Debug Session
⬇	Download

Button	Description
	Build

4.2 Installing GR5525 SDK

The GR5525 SDK is in a .zip file. You can access the details after extracting the file.

Note:

- SDK_Folder is the root directory of GR5525 SDK.
- Keil_Folder is the root directory of Keil.

4.3 Building a Bluetooth LE Application

This section introduces how to quickly build a custom Bluetooth LE application with Keil and GR5525 SDK.

4.3.1 Preparing ble_app_example

This section elaborates on how to create a project based on the template project provided in the GR5525 SDK.

Open `SDK_Folder\projects\ble\ble_peripheral\`, copy ble_app_template to the current directory, and rename it as **ble_app_example**. Change the base name of *.uvoptx* and *.uvprojx* files in `ble_app_example\Keil_5` to **ble_app_example**.

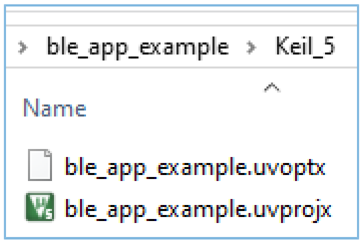
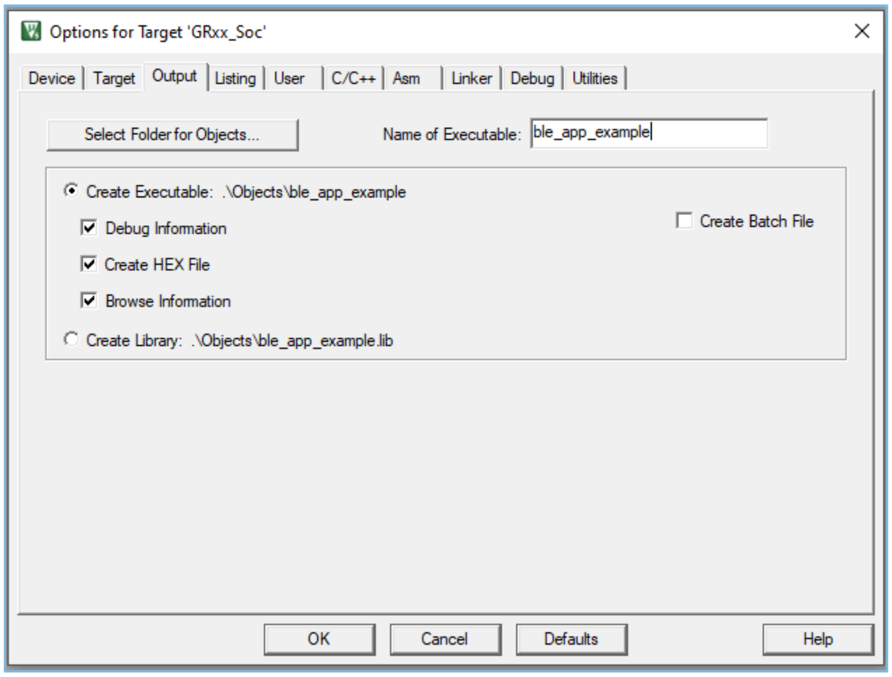


Figure 4-2 ble_app_example folder

Double-click *ble_app_example.uvprojx* to open the project example in Keil. Click , and the **Options for Target 'GRxx_Soc'** window opens. Choose the **Output** tab, and type **ble_app_example** in the **Name of Executable** field, to name the output file as **ble_app_example**.



Name of Executable: ble_app_example

(●) Create Executable: .\Objects\ble_app_example

[✓] Debug Information

[✓] Create HEX File

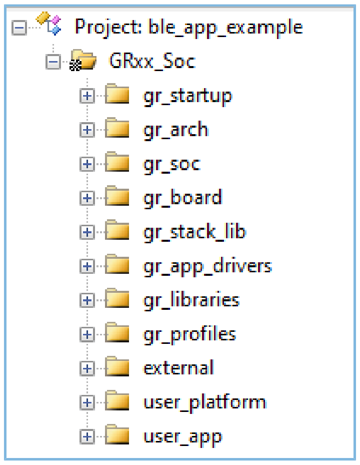
[✓] Browse Information

( ) Create Library: .\Objects\ble_app_example.lib

[ ] Create Batch File

Figure 4-3 Modifications to **Name of Executable**

All groups of the ble_app_example project are available in the **Project** window of Keil.



Project: ble_app_example
- GRxx_Soc
  - gr_startup
  - gr_arch
  - gr_soc
  - gr_board
  - gr_stack_lib
  - gr_app_drivers
  - gr_libraries
  - gr_profiles
  - external
  - user_platform
  - user_app

Figure 4-4 ble_app_example groups

Groups of the ble_app_example project are mainly in two categories: SDK groups and User groups.

- SDK groups

  The SDK groups include gr_startup, gr_arch, gr_soc, gr_board, gr_stack_lib, gr_app_drivers, gr_libraries, gr_profiles, and external.

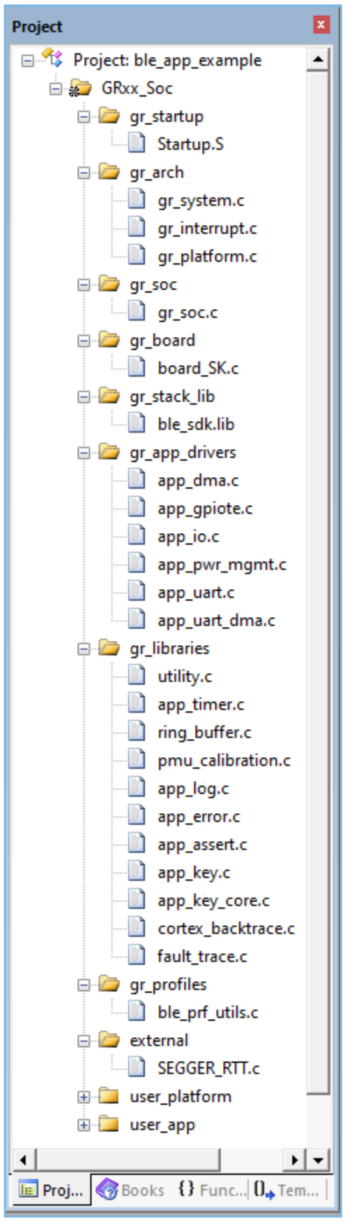


Figure 4-5 SDK groups

Source files in the SDK groups are not required to be modified. Group descriptions are provided below:

Table 4-2 SDK groups

SDK Group Name	Description
gr_startup	System boot file
gr_arch	Initialization configuration files and system interrupt API implementation files for System Core and PMU
gr_soc	*gr_soc.c* which is used for initializing and calibrating modules such as Clock, PMU, and Vector before entering the main() function
gr_board	Board-level description file which is used for implementing components such as log, key, and LED

SDK Group Name	Description
gr_stack_lib	GR5525 SDK .lib file
gr_app_drivers	Driver API source files which are easy to use for application developers. You can add related APP drivers on demand.
gr_libraries	Open source files of common assistant software modules and peripheral drivers provided in the SDK
gr_profiles	Source files of GATT Services/Service Clients. You can add necessary GATT source files for projects on demand.
external	Source files for third-party programs, such as FreeRTOS and SEGGER RTT. You can add third-party programs on demand.

- User groups

  User groups include user_platform and user_app.

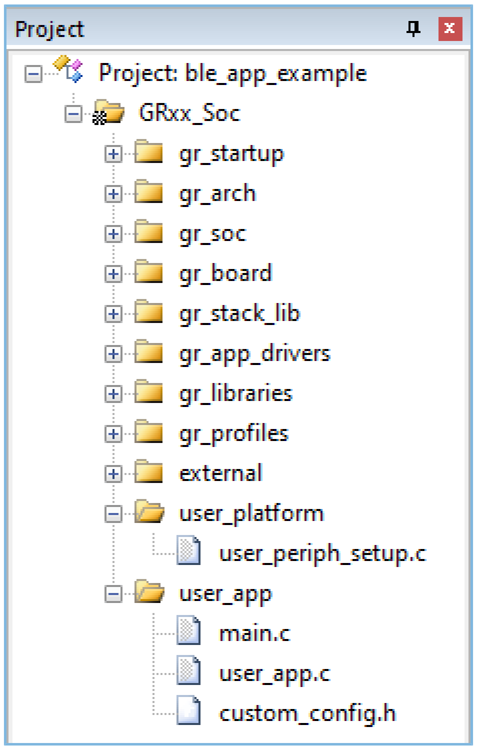


Figure 4-6 user_groups

Functionalities for source files in User groups need to be implemented by developers. Group descriptions are provided below:

Table 4-3 User groups

User Group Name	Description
user_platform	Software and hardware resource setting and application initialization; you need to execute corresponding APIs on demand.

User Group Name	Description
user_app	main() function entries and other source files created by developers, which are used to configure runtime parameters of Bluetooth LE Stack and execute event handlers of GATT Services/Service Clients

4.3.2 Configuring a Project

You should configure corresponding project options according to product characteristics, including NVDS, code running mode, memory layout, After Build, and other configuration items.

4.3.2.1 Configuring *custom_config.h*

custom_config.h is used to configure parameters of application projects. Developers can directly modify the configurations in the file or configure parameters in the **Configuration Wizard** interface of Keil.

Note:

custom_config.h of each application example project is in `Src\config` under the project directory.

- Modify the configurations in *custom_config.h*.

  GR5525 SDK provides a template configuration file *custom_config.h* (in `SDK_Folder\build\config\custom_config.h`). You can directly modify the template file to configure parameters for application projects.

Table 4-4 Parameters in *custom_config.h*

Macro	Description
SOC_GR5525	Define the SoC version number.
SYS_FAULT_TRACE_ENABLE	Enable/Disable trace info printing. If printing is enabled, the trace info is printed when a HardFault occurs. ◦ 0: Disable ◦ 1: Enable
ENABLE_BACKTRACE_FEA	Enable/Disable the stack backtrace functionality. ◦ 0: Disable ◦ 1: Enable
APP_DRIVER_USE_ENABLE	Enable/Disable the APP Drivers module. ◦ 0: Disable ◦ 1: Enable
APP_LOG_ENABLE	Enable/Disable the APP LOG module. ◦ 0: Disable ◦ 1: Enable
APP_LOG_STORE_ENABLE	Enable/Disable the APP LOG STORE module.

Macro	Description
	◦ 0: Disable ◦ 1: Enable
DTM_TEST_ENABLE	Enable/Disable DTM test. ◦ 0: Disable ◦ 1: Enable
PMU_CALIBRATION_ENABLE	Enable/Disable PMU calibration. When PMU calibration is enabled, the system monitors temperature and voltage automatically with adaptive adjustment. ◦ 0: Disable ◦ 1: Enable **Note:** PMU calibration shall be enabled in high/low temperature scenarios.
NVDS_START_ADDR	Start address of NVDS in Flash. By default, this macro is commented out in *cutom_config.h*. If you need to reconfigure the NVDS address, enable the macro and set the address as needed (4-KB alignment is compulsory). **Note:** The start address cannot be set in used areas in the memory (such as SCA and User App).
NVDS_NUM_SECTOR	Number of Flash sectors for NVDS
SYSTEM_STACK_SIZE	Size of Call Stack required by applications. The default value is 32 KB. You can set the value as needed. Please note that the value shall not be less than 6 KB. **Note:** After compilation of ble_app_example, the Maximum Stack Usage is provided in `Keil_5\Objects\ble_app_example.htm` for reference.
SYSTEM_HEAP_SIZE	Size of Heap required by applications. The default value is 16 KB. You can set the value as needed.
APP_CODE_LOAD_ADDR*	Start address of the application storage area **Note:** This address shall be within the Flash address range.
APP_CODE_RUN_ADDR*	Start address of the application running space If the value is the same as APP_CODE_LOAD_ADDR, applications run in XIP mode. If the value is within the RAM address range, applications run in mirror mode.
SYSTEM_CLOCK*	Set the system clock frequency. ◦ 0: 96 MHz ◦ 1: 64 MHz

Macro	Description
	◦ 2: 16 MHz (XO) ◦ 3: 48 MHz ◦ 4: 24 MHz ◦ 5: 16 MHz ◦ 6: 32 MHz (PLL)
CFG_LPCLK_INTERNAL_EN	Enable/Disable the OSC inside an SoC as the Bluetooth LE low-frequency sleep clock. If the OSC clock is enabled, CFG_LF_ACCURACY_PPM will be set to 500 ppm by force. ◦ 0: Disable ◦ 1: Enable
CFG_LF_ACCURACY_PPM	Bluetooth LE low-frequency sleep clock accuracy. The value shall range from 1 to 500 (unit: ppm).
BOOT_LONG_TIME*	Set 1-second delay (during SoC boot before implementing the second half Bootloader). ◦ 0: No delay ◦ 1: Delay for 1 second.
BOOT_CHECK_IMAGE	Determine whether to check the image during cold boot in XIP mode. ◦ 0: Do not check. ◦ 1: Check.
IO_LDO_USE_3P3_V	Enable/Disable LDO 3.3 V. ◦ 0: Disable ◦ 1: Enable
SECURITY_CFG_VAL	Configure the algorithm security level. ◦ 0: Level 1 ◦ 1: Level 2
CHIP_VER	Version of the SoC that the firmware runs on
CFG_CONTROLLER_ONLY	Use Bluetooth LE Controller only or not. ◦ 0: Use Bluetooth LE Controller and Host. ◦ 1: Use Bluetooth LE Controller only.
CFG_MAX_PRFS	Maximum number of GATT Profiles/Services supported by applications. You can set the value on demand. A larger value means occupying more RAM space.
CFG_MAX_BOND_DEVS	Maximum number of devices that can be bonded to applications; max.: 4
CFG_MAX_CONNECTIONS	Maximum number of devices that can be connected to applications; the number shall be no greater than 10. You can set the value based on needs. A larger value means more RAM space to be occupied by Bluetooth LE Stack Heaps. The size of Bluetooth LE Stack Heaps is

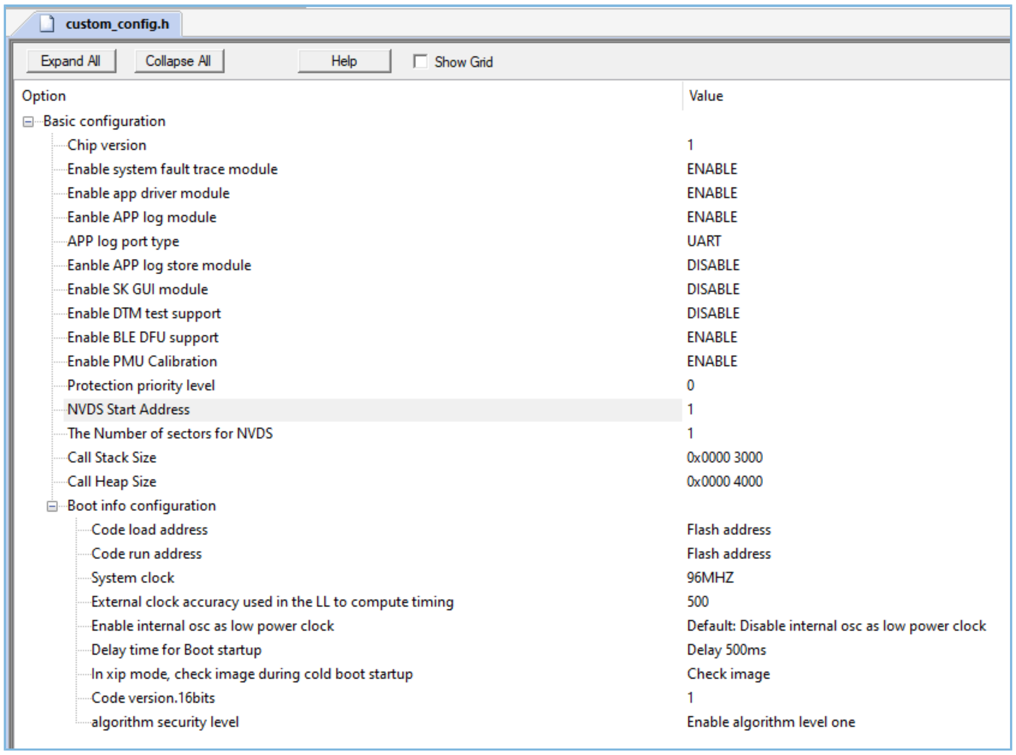
Macro	Description
	defined by the following four macros in *flash_scatter_config.h*, which cannot be changed by developers. ◦ ENV_HEAP_SIZE ◦ ATT_DB_HEAP_SIZE ◦ KE_MSG_HEAP_SIZE ◦ NON_RET_HEAP_SIZE
CFG_MAX_ADVS	Maximum number of Bluetooth LE legacy advertising and extended advertising supported by applications
CFG_MAX_SCAN	Support scanning or not. ◦ 0: No ◦ 1: Yes
CFG_MUL_LINK_WITH_SAME_DEV	Support multi-link functionality for a single device or not. ◦ 0: No ◦ 1: Yes
CFG_BT_BREDR	Support generating Bluetooth Classic link keys through the LE link or not. ◦ 0: No ◦ 1: Yes
CFG_CAR_KEY_SUPPORT	Support car key applications or not. ◦ 0: No ◦ 1: Yes
CFG_MASTER_SUPPORT	Support master role or not. ◦ 0: No ◦ 1: Yes
CFG_SLAVE_SUPPORT	Support slave role or not. ◦ 0: No ◦ 1: Yes
CFG_LEGACY_PAIR_SUPPORT	Support legacy pairing or not. ◦ 0: No ◦ 1: Yes
CFG_SC_PAIR_SUPPORT	Support secure pairing or not. ◦ 0: No ◦ 1: Yes
CFG_COC_SUPPORT	Support Connection-oriented Channel (COC) or not.

Macro	Description
	◦ 0: No ◦ 1: Yes
CFG_GATTS_SUPPORT	Support GATT Server module or not. ◦ 0: No ◦ 1: Yes
CFG_GATTC_SUPPORT	Support GATT Client module or not. ◦ 0: No ◦ 1: Yes
CFG_RANGING_SUPPORT	Support ranging or not. ◦ 0: No ◦ 1: Yes

*: Macros marked with an asterisk (*) in the table above are used to initialize the BUILD_IN_APP_INFO structure which is defined at 0x200 in the firmware and is initialized with the macros in *custom_config.h*. When the system boots, the Bootloader reads value from 0x200 and uses it as a boot parameter.

- Configure parameters in the **Configuration Wizard** interface.

  Comments in *custom_config.h* are compliant with Configuration Wizard Annotations of Keil, making it possible for developers to open *custom_config.h* in Keil and configure application project parameters in the **Configuration Wizard** interface of Keil.



Option	Value
Basic configuration	
Chip version	1
Enable system fault trace module	ENABLE
Enable app driver module	ENABLE
Eanble APP log module	ENABLE
APP log port type	UART
Eanble APP log store module	DISABLE
Enable SK GUI module	DISABLE
Enable DTM test support	DISABLE
Enable BLE DFU support	ENABLE
Enable PMU Calibration	ENABLE
Protection priority level	0
NVDS Start Address	1
The Number of sectors for NVDS	1
Call Stack Size	0x0000 3000
Call Heap Size	0x0000 4000
Boot info configuration	
Code load address	Flash address
Code run address	Flash address
System clock	96MHZ
External clock accuracy used in the LL to compute timing	500
Enable internal osc as low power clock	Default: Disable internal osc as low power clock
Delay time for Boot startup	Delay 500ms
In xip mode, check image during cold boot startup	Check image
Code version.16bits	1
algorithm security level	Enable algorithm level one

Figure 4-7 *custom_config.h* in the **Configuration Wizard** interface

4.3.2.2 Configuring Memory Layout

In a Keil project, the memory area for the linker is defined in scatter (.sct) files. The GR5525 SDK provides an example scatter file (`SDK_Folder\platform\soc\linker\keil\flash_scatter_common.sct`) to help developers quickly configure memory layout. The macros used by *flash_scatter_common.sct* are defined in *flash_scatter_config.h*.

Note:

In Keil, `__attribute__((section("name")))` can be used to define a function or a variable in a specific memory segment, in which **name** can be customized by developers. The scatter (*.sct*) file defines the location for customized fields. For example, to define the Zero-Initialized (ZI) data of applications in the segment named as **.bss.app**, you can set **attribute** to `__attribute__((section(".bss.app")))`.

You can follow the steps below to configure the memory layout:

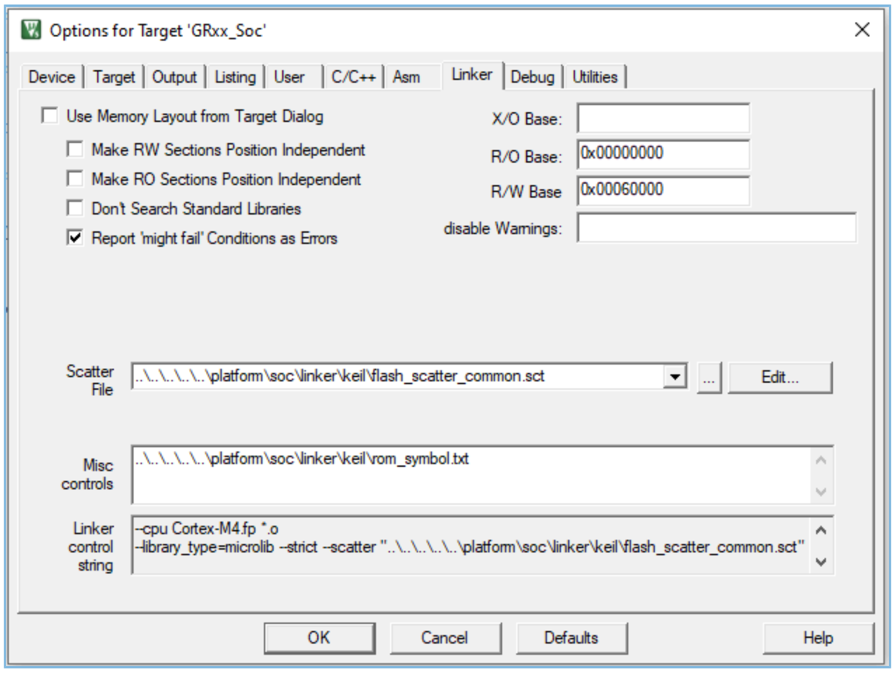
1. Click (**Options for Target**) on the Keil toolbar and open the **Options for Target 'GRxx_Soc'** dialog box. Select the **Linker** tab.

2. On the **Scatter File** bar of the **Linker** tab, click **...** to browse and select the *flash_scatter_common.sct* file in SDK_ `Folder\platform\soc\linker\keil`. You can also copy the scatter (.sct) file and the configuration (.h) file to the ble_app_example project directory and then select the scatter file.

Note:

`#! armcc -E -I` in *flash_scatter_common.sct* specifies the directory of the header file on which *flash_scatter_common.sct* depends. A wrong path results in a linker error.

3. Click **Edit...** to open the .sct file, and modify corresponding code based on practical product memory layout.



- [ ] Use Memory Layout from Target Dialog
- [ ] Make RW Sections Position Independent
- [ ] Make RO Sections Position Independent
- [ ] Don't Search Standard Libraries
- [x] Report 'might fail' Conditions as Errors

X/O Base:
R/O Base: 0x00000000
R/W Base 0x00060000
disable Warnings:

Scatter File: ..\..\..\..\..\platform\soc\linker\keil\flash_scatter_common.sct

Misc controls: ..\..\..\..\..\platform\soc\linker\keil\rom_symbol.txt

Linker control string:

```
--cpu Cortex-M4.fp *.o
--library_type=microlib --strict --scatter "..\..\..\..\..\platform\soc\linker\keil\flash_scatter_common.sct"
```

Figure 4-8 Configuration of scatter file

4. Click **OK** to save the settings.

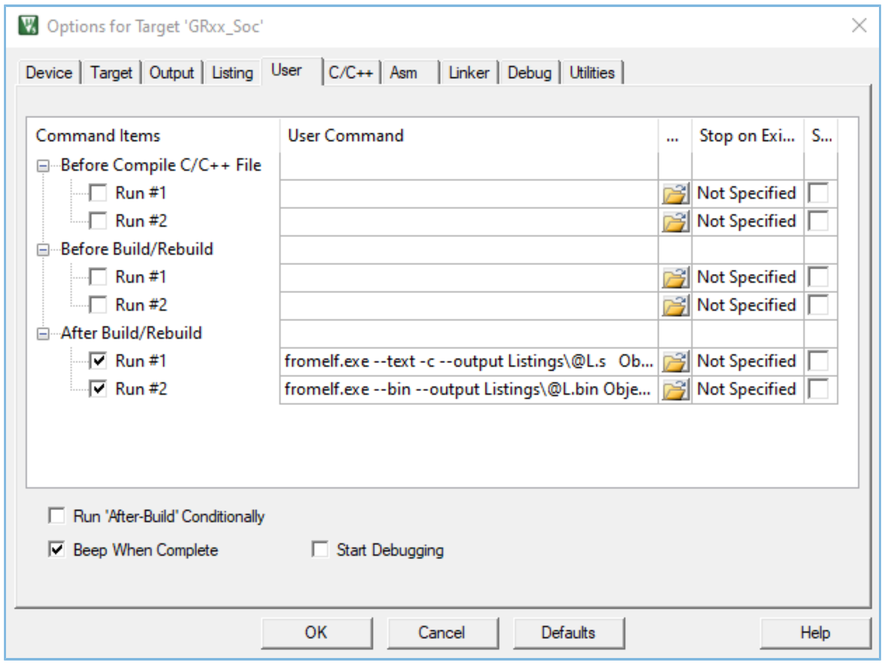
4.3.2.3 Configuring After Build

After Build in Keil can specify the command to be executed after a project is built.

By default, After Build has been configured for the ble_app_template project. Therefore, ble_app_example, which is based on ble_app_template, does not require manual configuration of After Build.

If you build a project in Keil, follow the steps below to configure **After Build**:

1. Click (**Options for Target**) on the Keil toolbar and open the **Options for Target 'GRxx_Soc'** dialog box. Select the **User** tab.
2. From the options expanded from **After Build/Rebuild**, select **Run #1**, and type **fromelf.exe --text -c --output Listings\@L.s Objects\@L.axf** in the corresponding **User Command** field. This step helps you utilize Keil fromelf to generate a compiling file based on the selected .axf file.
3. From the options expanded from **After Build/Rebuild**, select **Run #2**, and type **fromelf.exe --bin --output Listings \@L.bin Objects\@L.axf** in the corresponding **User Command** field. This step helps you utilize Keil fromelf to generate a compiling file based on the selected .axf file.
4. Click **OK** to save the settings.


Options for Target 'GRxx_Soc'

Device | Target | Output | Listing | User | C/C++ | Asm | Linker | Debug | Utilities

Command Items	User Command	...	Stop on Exi...	S...
Before Compile C/C++ File				
☐ Run #1			Not Specified	☐
☐ Run #2			Not Specified	☐
Before Build/Rebuild				
☐ Run #1			Not Specified	☐
☐ Run #2			Not Specified	☐
After Build/Rebuild				
☑ Run #1	fromelf.exe --text -c --output Listings\@L.s Ob...		Not Specified	☐
☑ Run #2	fromelf.exe --bin --output Listings\@L.bin Obje...		Not Specified	☐

☐ Run 'After-Build' Conditionally

☑ Beep When Complete ☐ Start Debugging

Figure 4-9 Configuration of After Build

4.3.3 Adding User Code

You can modify corresponding code in ble_app_example on demand.

4.3.3.1 Modifying the main() Function

Code of a typical *main.c* file is provided as follows:

```
/**@brief Stack global variables for Bluetooth protocol stack. */
STACK_HEAP_INIT(heaps_table);
…
int main (void)
{
    /** Initialize user peripherals. */
    app_periph_init();

    /** Initialize BLE Stack. */
    ble_stack_init(&&m_app_ble_callback, &heaps_table);

    // Main Loop
    while (1)
    {
        app_log_flush();
        pwr_mgmt_schedule();
    }
}
```

- `STACK_HEAP_INIT(heaps_table)` defines seven global arrays as Heaps for Bluetooth LE Stack. Do not modify the definition; otherwise, Bluetooth LE Stack may not work properly. The Heap size is determined by the Bluetooth LE service volume in "Section 4.3.2.1 Configuring custom_config.h".

- `app_periph_init()` is used to initialize peripherals. In development and debugging phases, SYS_SET_BD_ADDR in this function can be used to set a temporary Public Address; pwr_mgmt_mode_set() sets the MCU operation mode (SLEEP/IDLE/ACTIVE) during automatic power management; app_periph_init() is implemented in *user_periph_setup.c*, and the example code is as follows.

```
/**@brief Bluetooth device address. */
static const uint8_t s_bd_addr[SYS_BD_ADDR_LEN] = {0x11, 0x11, 0x11, 0x11,0x11, 0x11};
…
void app_periph_init(void)
{
   SYS_SET_BD_ADDR(s_bd_addr);
   bsp_log_init();
   pwr_mgmt_mode_set(PMR_MGMT_IDLE_MODE);
}
```

- Add main loop code of applications to `while(1) { }`, for example, code to handle external input and update GUI.
- To use the APP LOG module, call `app_log_flush()` in the main loop, to ensure logs are output completely before the system enters sleep state. For more information about the APP LOG module, refer to "Section 4.6.3 Outputting Debug Logs".
- Call `pwr_mgmt_shcedule()` to implement automatic power management to reduce system power consumption.

4.3.3.2 Implementing Bluetooth LE Service Logics

Bluetooth LE service logics of applications are driven by a number of Bluetooth LE events which are defined in GR5525 SDK. Therefore, applications need to implement the corresponding event handlers in GR5525 SDK to obtain operation results or state change notifications of Bluetooth LE Stack. The event handlers are called in the interrupt context of Bluetooth LE SDK IRQ. Therefore, do not perform long-running operations in handlers, for example, blocking function call and infinite loop; otherwise, the system is blocked, causing Bluetooth LE Stack and the SDK Bluetooth LE module unable to run in a normal timing.

Bluetooth LE events fall into eight categories: Common, GAP Management, GAP Connection Control, Security Manager, L2CAP, GATT Common, GATT Server, and GATT Client. All Bluetooth LE events supported by GR5525 SDK are listed below.

Table 4-5 Bluetooth LE events

Event Type	Event Name	Description
Common	BLE_COMMON_EVT_STACK_INIT	Bluetooth LE Stack init complete event
GAP Management	BLE_GAPM_EVT_CH_MAP_SET	Channel Map Set complete event
	BLE_GAPM_EVT_WHITELIST_SET	Whitelist Set complete event
	BLE_GAPM_EVT_PER_ADV_LIST_SET	Periodic Advertising List Set complete event

Event Type	Event Name	Description
	BLE_GAPM_EVT_PRIVACY_MODE_SET	Privacy Mode for Peer Device Set complete event
	BLE_GAPM_EVT_LEPSM_REGISTER	LEPSM Register complete event
	BLE_GAPM_EVT_LEPSM_UNREGISTER	LEPSM Unregister complete event
	BLE_GAPM_EVT_DEV_INFO_GOT	Device Info Get event
	BLE_GAPM_EVT_ADV_START	Advertising Start complete event
	BLE_GAPM_EVT_ADV_STOP	Advertising Stop complete event
	BLE_GAPM_EVT_SCAN_REQUEST	Scan Request event
	BLE_GAPM_EVT_ADV_DATA_UPDATE	Advertising Data update event
	BLE_GAPM_EVT_SCAN_START	Scan Start complete event
	BLE_GAPM_EVT_SCAN_STOP	Scan Stop complete event
	BLE_GAPM_EVT_ADV_REPORT	Advertising Report event
	BLE_GAPM_EVT_SYNC_ESTABLISH	Periodic Advertising Synchronization Establish event
	BLE_GAPM_EVT_SYNC_STOP	Periodic Advertising Synchronization Stop event
	BLE_GAPM_EVT_SYNC_LOST	Periodic Advertising Synchronization Lost event
	BLE_GAPM_EVT_READ_RSLV_ADDR	Read Resolvable Address event
GAP Connection Control	BLE_GAPC_EVT_PHY_UPDATED	PHY Update event
	BLE_GAPC_EVT_CONNECTED	Connected event
	BLE_GAPC_EVT_DISCONNECTED	Disconnected event
	BLE_GAPC_EVT_CONNECT_CANCEL	Connect Cancel event
	BLE_GAPC_EVT_AUTO_CONN_TIMEOUT	Auto Connect Timeout event
	BLE_GAPC_EVT_CONN_PARAM_UPDATED	Connect Parameter Updated event
	BLE_GAPC_EVT_CONN_PARAM_UPDATE_REQ	Connect Parameter Request event
	BLE_GAPC_EVT_PEER_NAME_GOT	Peer Name Get event
	BLE_GAPC_EVT_CONN_INFO_GOT	Connect Info Get event
	BLE_GAPC_EVT_PEER_INFO_GOT	Peer Info Get event
	BLE_GAPC_EVT_DATA_LENGTH_UPDATED	Data Length Updated event
	BLE_GAPC_EVT_DEV_INFO_SET	Device Info Set event
	BLE_GAPC_EVT_CONNECT_IQ_REPORT	Connection IQ Report info event
	BLE_GAPC_EVT_CONNECTLESS_IQ_REPORT	Connectionless IQ Report info event

Event Type	Event Name	Description
	BLE_GAPC_EVT_LOCAL_TX_POWER_READ	Local transmit power read indication info event
	BLE_GAPC_EVT_REMOTE_TX_POWER_READ	Remote transmit power read indication info event
	BLE_GAPC_EVT_TX_POWER_CHANGE_REPORT	Transmit power change reporting info event
	BLE_GAPC_EVT_PATH_LOSS_THRESHOLD_REPORT	Path loss threshold reporting info event
	BLE_GAPC_EVT_RANGING_IND	Ranging indication event
	BLE_GAPC_EVT_RANGING_SAMPLE_REPORT	Ranging sample report event
	BLE_GAPC_EVT_RANGING_CMP_IND	Ranging complete indication event
	BLE_GAPC_EVT_DFT_SUBRATE_SET	Default subrate param set complete event
	BLE_GAPC_EVT_SUBRATE_CHANGE_IND	Subrate change indication event
GATT Common	BLE_GATT_COMMON_EVT_MTU_EXCHANGE	MTU Exchange event
	BLE_GATT_COMMON_EVT_PRF_REGISTER	Service Register event
GATT Server	BLE_GATTS_EVT_READ_REQUEST	GATTS Read Request event
	BLE_GATTS_EVT_WRITE_REQUEST	GATTS Write Request event
	BLE_GATTS_EVT_PREP_WRITE_REQUEST	GATTS Prepare Write Request event
	BLE_GATTS_EVT_NTF_IND	GATTS Notify or Indicate Complete event
	BLE_GATTS_EVT_CCCD_RECOVERY	GATTS CCCD Recovery event
	BLE_GATTS_EVT_MULT_NTF	GATTS Multiple Notifications event
	BLE_GATTS_EVT_ENH_READ_REQUEST	GATTS Enhanced Read Request event
	BLE_GATTS_EVT_ENH_WRITE_REQUEST	GATTS Enhanced Write Request event
	BLE_GATTS_EVT_ENH_PREP_WRITE_REQUEST	GATTS Enhanced Prepare Write Request event
	BLE_GATTS_EVT_ENH_NTF_IND	GATTS Enhanced Notify or Indicate Complete event
	BLE_GATTS_EVT_ENH_CCCD_RECOVERY	GATTS Enhanced CCCD Recovery event

Event Type	Event Name	Description
	BLE_GATTS_EVT_ENH_MULT_NTF	GATTS Enhanced Multiple Notifications event
GATT Client	BLE_GATTC_EVT_SRVC_BROWSE	GATTC Service Browse event
	BLE_GATTC_EVT_PRIMARY_SRVC_DISC	GATTC Primary Service Discovery event
	BLE_GATTC_EVT_INCLUDE_SRVC_DISC	GATTC Include Service Discovery event
	BLE_GATTC_EVT_CHAR_DISC	GATTC Characteristic Discovery event
	BLE_GATTC_EVT_CHAR_DESC_DISC	GATTC Characteristic Descriptor Discovery event
	BLE_GATTC_EVT_READ_RSP	GATTC Read Response event
	BLE_GATTC_EVT_WRITE_RSP	GATTC Write Response event
	BLE_GATTC_EVT_NTF_IND	GATTC Notify or Indicate Receive event
	BLE_GATTC_EVT_CACHE_UPDATE	GATTC Cache Update event
	BLE_GATTC_EVT_ENH_SRVC_BROWSE	GATTC Enhanced Service Browse event
	BLE_GATTC_EVT_ENH_PRIMARY_SRVC_DISC	GATTC Enhanced Primary Service Discovery event
	BLE_GATTC_EVT_ENH_INCLUDE_SRVC_DISC	GATTC Enhanced Include Service Discovery event
	BLE_GATTC_EVT_ENH_CHAR_DISC	GATTC Enhanced Characteristic Discovery event
	BLE_GATTC_EVT_ENH_CHAR_DESC_DISC	GATTC Enhanced Characteristic Descriptor Discovery event
	BLE_GATTC_EVT_ENH_READ_RSP	GATTC Enhanced Read Response event
	BLE_GATTC_EVT_ENH_WRITE_RSP	GATTC Enhanced Write Response event
	BLE_GATTC_EVT_ENH_NTF_IND	GATTC Enhanced Notify or Indicate Receive event
Security Manager	BLE_SEC_EVT_LINK_ENC_REQUEST	Link Encrypted Request event
	BLE_SEC_EVT_LINK_ENCRYPTED	Link Encrypted event
	BLE_SEC_EVT_KEY_PRESS_NTF	Key Press event

Event Type	Event Name	Description
	BLE_SEC_EVT_KEY_MISSING	Key Missing event
L2CAP	BLE_L2CAP_EVT_CONN_REQ	L2CAP Connect Request event
	BLE_L2CAP_EVT_CONN_IND	L2CAP Connected Indicate event
	BLE_L2CAP_EVT_ADD_CREDITS_IND	L2CAP Credits Add Indicate event
	BLE_L2CAP_EVT_DISCONNECTED	L2CAP Disconnected event
	BLE_L2CAP_EVT_SDU_RECV	L2CAP SDU Receive event
	BLE_L2CAP_EVT_SDU_SEND	L2CAP SDU Send event
	BLE_L2CAP_EVT_ADD_CREDITS_CPLT	L2CAP Credits Add Completed event
	BLE_L2CAP_EVT_ENH_CONN_REQ	L2CAP Enhanced Connect Request event
	BLE_L2CAP_EVT_ENH_CONN_IND	L2CAP Enhanced Connected Indicate event
	BLE_L2CAP_EVT_ENH_RECONFIG_CPLT	L2CAP Enhanced Reconfig Completed event
	BLE_L2CAP_EVT_ENH_RECONFIG_IND	L2CAP Enhanced Reconfig Indicate event

You need to implement necessary Bluetooth LE event handlers according to functional requirements of your products. For example, if a product does not support Security Manager, you do not need to implement corresponding events; if the product supports GATT Server only, you do not need to implement the events corresponding to GATT Client. Only those event handlers required for products are to be implemented.

Tip:

For details about the usage of Bluetooth LE APIs and event APIs, refer to the source code of Bluetooth LE examples in `SDK_Folder\documentation\GR5525_API_Reference` and `SDK_Folder\projects\ble`.

4.3.3.3 Scheduling BLE_Stack_IRQ, BLE_SDK_IRQ, and Applications

Bluetooth LE Stack is the core to implement Bluetooth LE protocols. It can directly operate the Bluetooth 5.3 Core (refer to "Section 2.2 Software Architecture"). Therefore, BLE_Stack_IRQ has the second-highest priority after SVCall IRQ, which ensures that Bluetooth LE Stack runs strictly in a timing specified in *Bluetooth Core Spec*.

A state change of Bluetooth LE Stack triggers the BLE_SDK_IRQ interrupt with lower priority. In this interrupt handler, the Bluetooth LE event handlers (to be executed in applications) are called to send state change notifications of Bluetooth LE Stack and related service data to applications. Avoid time-consuming operations when using these event handlers. Perform such operations in the main loop or in user-level threads instead. You can use the module in `SDK_Folder\components\libraries\app_queue`, or your own application framework, to transfer events from Bluetooth LE event handlers to the main loop.

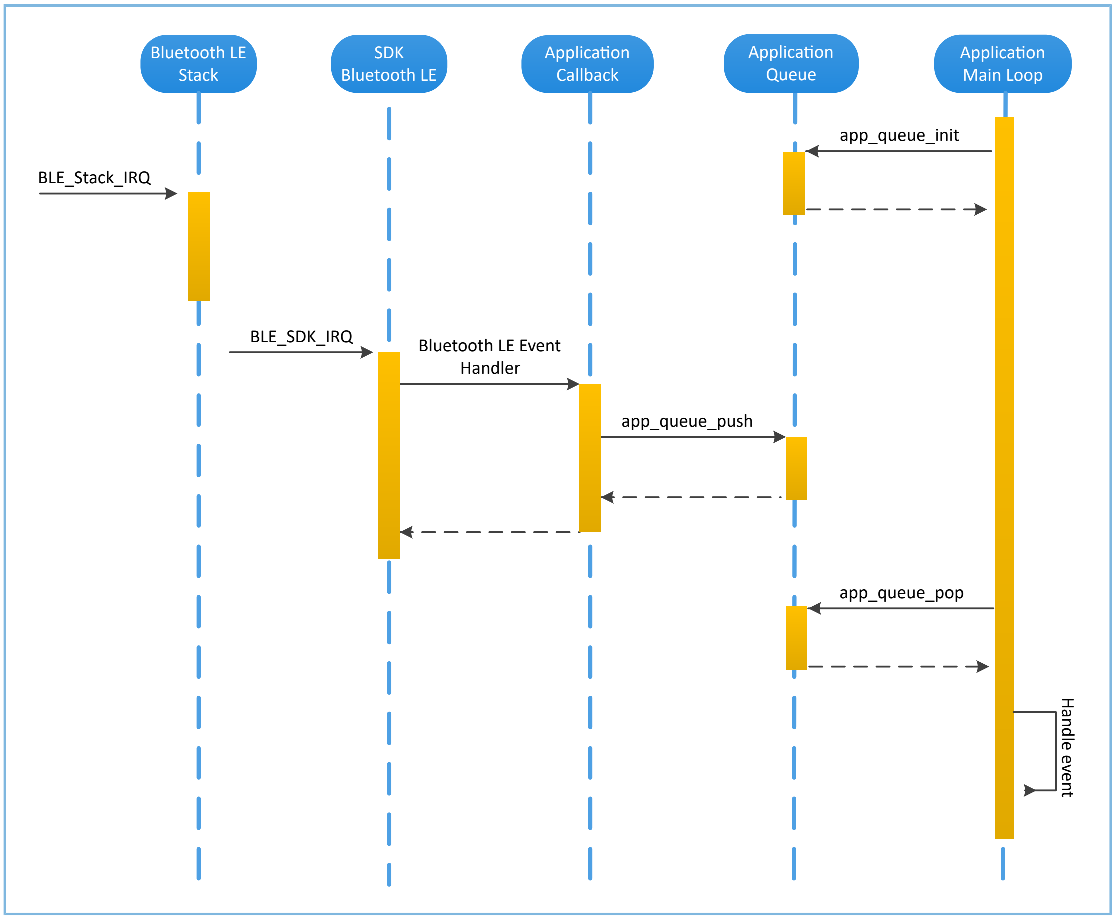


Figure 4-10 System schedule (without OS)

4.4 Generating Firmware

After building a Bluetooth LE application, you can directly click (**Build**) on the Keil toolbar to build a project. After project compilation is completed, two firmware files (in .bin and .hex formats) are created in `Keil_5\Listings` and `Keil_5\Objects` respectively in the project directory.

Table 4-6 Firmware files generated

Name	Description
ble_app_example.bin	Binary application firmware, can be downloaded to Flash through GProgrammer for running
ble_app_example.hex	Binary application firmware, can be downloaded to Flash through Keil or GProgrammer for running

Tip:

Both the two types of firmware can be downloaded to Flash through GProgrammer for running. Refer to *GProgrammer User Manual* for details.

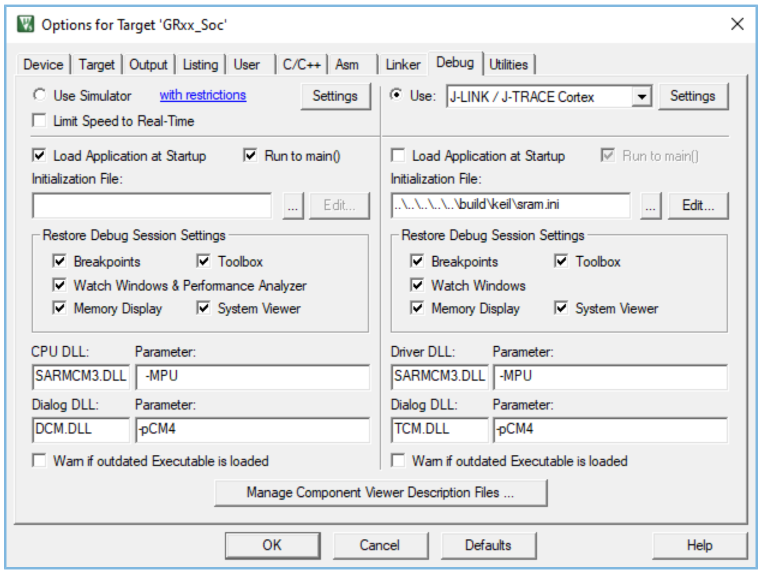
4.5 Downloading .hex Files to Flash

After a firmware file is are generated, you need to download the file to Flash. Specific steps are provided below:

1. Configure Keil Flash programming algorithm.

   (1) Copy `SDK_Folder\build\binaries\download_algorithm\Keil\GR5xxx_16MB_Flash.FLM` to `Keil_Folder\ARM\Flash`.

   (2) Click (**Options for Target**) on the Keil toolbar, open the **Options for Target 'GRxx_Soc'** dialog box, and select the **Debug** tab. Click **Settings** on the right side of **Use: J-LINK/J-TRACE Cortex**.



Options for Target 'GRxx_Soc'

Device | Target | Output | Listing | User | C/C++ | Asm | Linker | Debug | Utilities

○ Use Simulator with restrictions Settings
☐ Limit Speed to Real-Time
☑ Load Application at Startup ☑ Run to main()
Initialization File:
Restore Debug Session Settings
☑ Breakpoints ☑ Toolbox
☑ Watch Windows & Performance Analyzer
☑ Memory Display ☑ System Viewer
CPU DLL: SARMCM3.DLL Parameter: -MPU
Dialog DLL: DCM.DLL Parameter: -pCM4
☐ Warn if outdated Executable is loaded

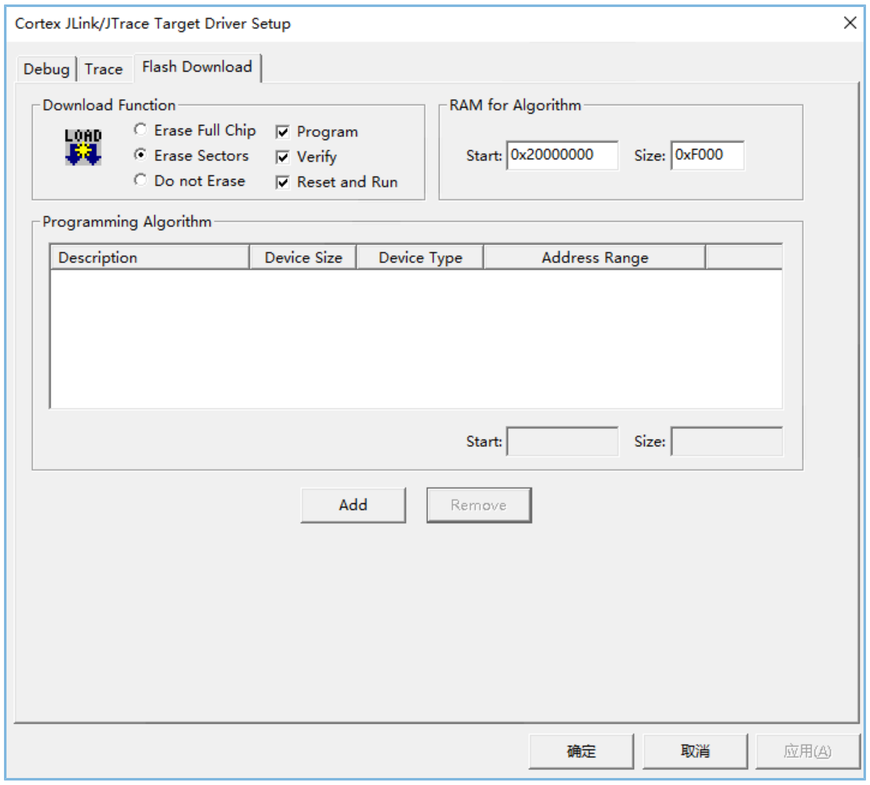
● Use: J-LINK / J-TRACE Cortex Settings
☐ Load Application at Startup ☑ Run to main()
Initialization File: ..\..\..\..\..\build\keil\sram.ini
Restore Debug Session Settings
☑ Breakpoints ☑ Toolbox
☑ Watch Windows
☑ Memory Display ☑ System Viewer
Driver DLL: SARMCM3.DLL Parameter: -MPU
Dialog DLL: TCM.DLL Parameter: -pCM4
☐ Warn if outdated Executable is loaded

Manage Component Viewer Description Files ...

OK | Cancel | Defaults | Help

Figure 4-11 **Debug** tab

   (3) In the **Cortex JLink/JTrace Target Driver Setup** window, select **Flash Download**. In the **Download Function** pane, you can set the erase type and check optional items: **Program**, **Verify**, and **Reset and Run**. Default configurations of Keil are shown below:


Cortex JLink/JTrace Target Driver Setup

Debug | Trace | Flash Download

Download Function
- Erase Full Chip [✓ Erase Sectors] Do not Erase
- [✓] Program
- [✓] Verify
- [✓] Reset and Run

RAM for Algorithm: Start: 0x20000000 Size: 0xF000

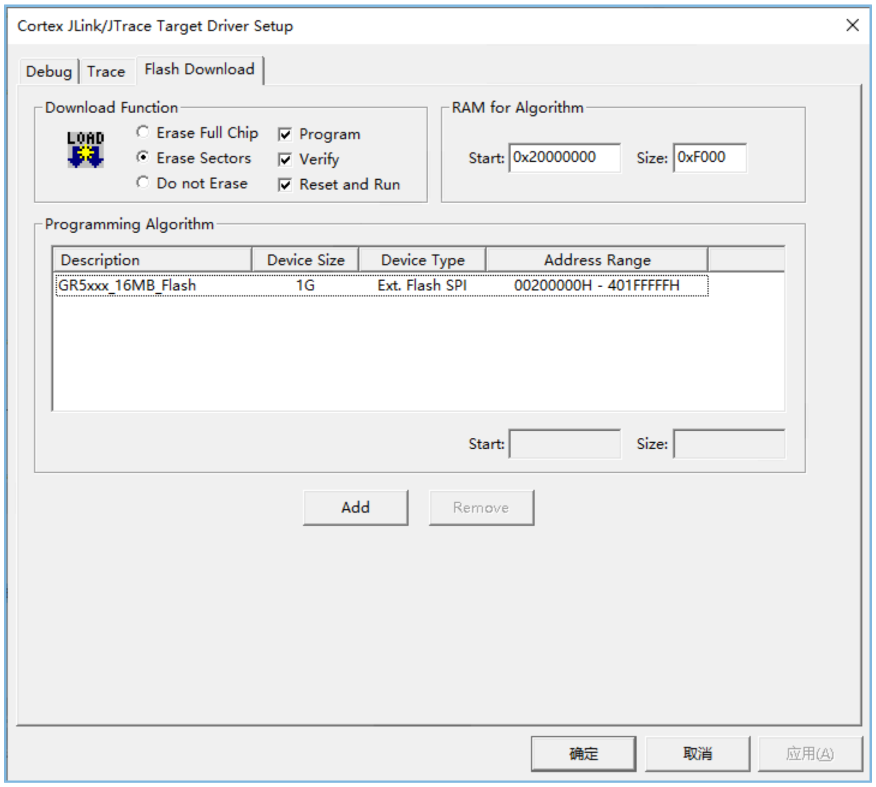
Programming Algorithm

Description	Device Size	Device Type	Address Range

Start: Size:

Figure 4-12 Default configurations in the **Download Function** pane

(4) Click **Add** to add *GR5xxx_16MB_Flash.FLM* (in `SDK_Folder\build\keil\`) to **Programming Algorithm**.



Download Function: ( ) Erase Full Chip [✓ Erase Sectors] ( ) Do not Erase; ☑ Program ☑ Verify ☑ Reset and Run

RAM for Algorithm: Start: 0x20000000 Size: 0xF000

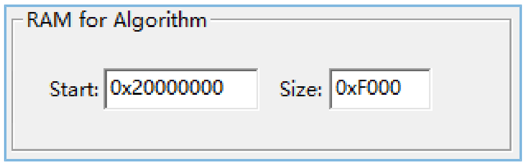
Programming Algorithm

Description	Device Size	Device Type	Address Range
GR5xxx_16MB_Flash	1G	Ext. Flash SPI	00200000H - 401FFFFFH

Start: Size:

Figure 4-13 Adding *GR5xxx_16MB_Flash.FLM* to **Programming Algorithm**

(5) Configure **RAM for Algorithm**, which defines address space to load and implement the programming algorithm. Enter the start address of RAM in GR5525 in the **Start** input field: **0x20000000**. Enter **0xF000** in the **Size** input field.



RAM for Algorithm

Start: 0x20000000 Size: 0xF000

Figure 4-14 Settings of **RAM for Algorithm**

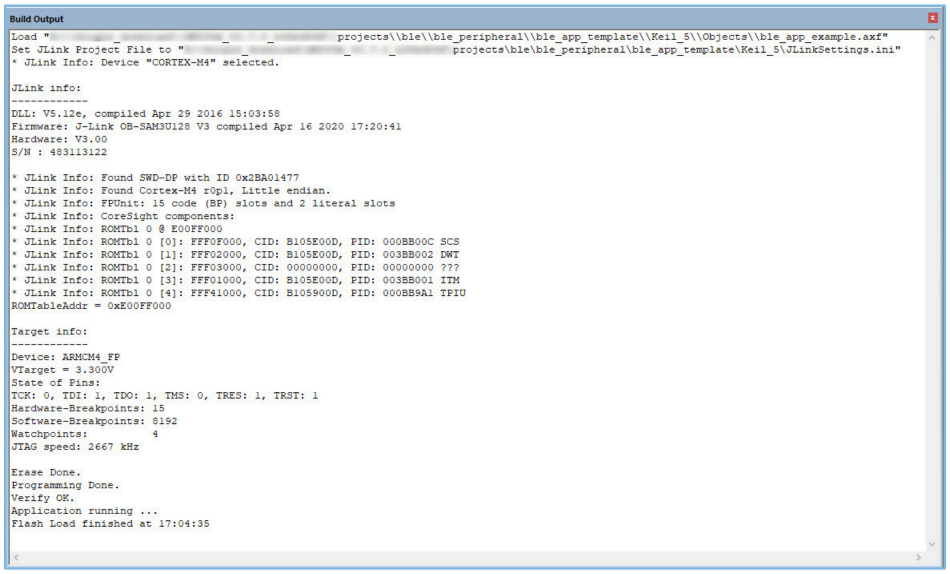
(6) Click **OK** to save the settings.

2. Download firmware.

After completing configuration, click (**Download**) on the Keil toolbar to download *ble_app_example.axf* to Flash. After download is completed, the following results are displayed in the **Build Output** window of Keil.

Note:

During file download, if **No Cortex-M SW Device Found** pops up, it indicates the SoC may be in sleep state at that moment (the firmware with sleep mode enabled is running), so the .hex file cannot be downloaded to Flash. In this case, developers need to press **RESET** on the GR5525 SK Board and wait for about 1 second; then click (**Download**) to download the file again.



Build Output

```
Load "[redacted]projects\\ble\\ble_peripheral\\ble_app_template\\Keil_5\\Objects\\ble_app_example.axf"
Set JLink Project File to "[redacted]projects\ble\ble_peripheral\ble_app_template\Keil_5\JLinkSettings.ini"
* JLink Info: Device "CORTEX-M4" selected.

JLink info:
------------
DLL: V5.12e, compiled Apr 29 2016 15:03:58
Firmware: J-Link OB-SAM3U128 V3 compiled Apr 16 2020 17:20:41
Hardware: V3.00
S/N : 483113122

* JLink Info: Found SWD-DP with ID 0x2BA01477
* JLink Info: Found Cortex-M4 r0p1, Little endian.
* JLink Info: FPUnit: 15 code (BP) slots and 2 literal slots
* JLink Info: CoreSight components:
* JLink Info: ROMTbl 0 @ E00FF000
* JLink Info: ROMTbl 0 [0]: FFF0F000, CID: B105E00D, PID: 000BB00C SCS
* JLink Info: ROMTbl 0 [1]: FFF02000, CID: B105E00D, PID: 003BB002 DWT
* JLink Info: ROMTbl 0 [2]: FFF03000, CID: 00000000, PID: 00000000 ???
* JLink Info: ROMTbl 0 [3]: FFF01000, CID: B105E00D, PID: 003BB001 ITM
* JLink Info: ROMTbl 0 [4]: FFF41000, CID: B105900D, PID: 000BB9A1 TPIU
ROMTableAddr = 0xE00FF000

Target info:
------------
Device: ARMCM4_FP
VTarget = 3.300V
State of Pins:
TCK: 0, TDI: 1, TDO: 1, TMS: 0, TRES: 1, TRST: 1
Hardware-Breakpoints: 15
Software-Breakpoints: 8192
Watchpoints:          4
JTAG speed: 2667 kHz

Erase Done.
Programming Done.
Verify OK.
Application running ...
Flash Load finished at 17:04:35
```

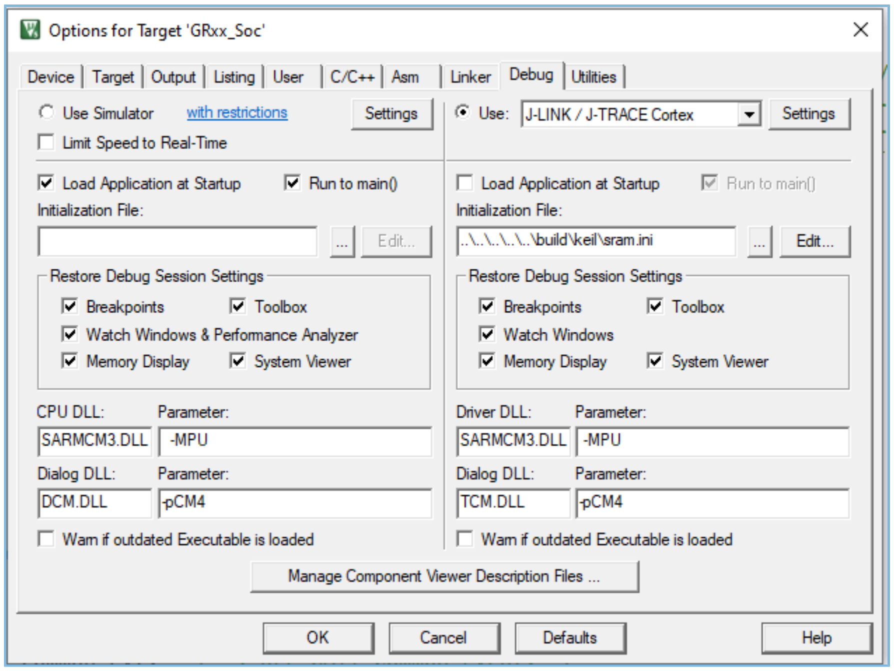
Figure 4-15 Download results

4.6 Debugging

Keil provides a debugger for online code debugging. The debugger supports setting six hardware breakpoints and multiple software breakpoints. It also provides developers with multiple methods to set debug commands.

4.6.1 Configuring the Debugger

Configure the debugger before debugging. Click (**Options for Target**) on the Keil toolbar, open the **Options for Target 'GRxx_Soc'** dialog box, and select the **Debug** tab. In the window, software simulation debugging configurations display on the left side, and online hardware debugging configurations display on the right side. Bluetooth LE example projects adopt the online hardware debugging. Related default configurations of the debugger are shown as follows:


Options for Target 'GRxx_Soc'

Device | Target | Output | Listing | User | C/C++ | Asm | Linker | Debug | Utilities

[ ] Use Simulator with restrictions Settings
[ ] Limit Speed to Real-Time
[✓] Load Application at Startup [✓] Run to main()
Initialization File:

Restore Debug Session Settings
[✓] Breakpoints [✓] Toolbox
[✓] Watch Windows & Performance Analyzer
[✓] Memory Display [✓] System Viewer

CPU DLL: SARMCM3.DLL Parameter: -MPU
Dialog DLL: DCM.DLL Parameter: -pCM4
[ ] Warn if outdated Executable is loaded

[✓ Use:] J-LINK / J-TRACE Cortex Settings
[ ] Load Application at Startup [✓] Run to main()
Initialization File: ..\..\..\..\..\build\keil\sram.ini Edit...

Restore Debug Session Settings
[✓] Breakpoints [✓] Toolbox
[✓] Watch Windows
[✓] Memory Display [✓] System Viewer

Driver DLL: SARMCM3.DLL Parameter: -MPU
Dialog DLL: TCM.DLL Parameter: -pCM4
[ ] Warn if outdated Executable is loaded

Manage Component Viewer Description Files ...

OK Cancel Defaults Help

Figure 4-16 Configuring the debugger

The default initialization file *sram.ini* is in `SDK_Folder\build\keil`. You can use this file directly, or copy it to the project directory.

The initialization file *sram.ini* contains a set of debug commands, which are executed during debugging. On the **Initialization File** bar, click **Edit...** on the right side, to open *sram.ini*. Example code of *sram.ini* is provided as follows:

```
/**
*****************************************************************
* GR55xx object loading script through debugger interface
* (e.g.Jlink, *etc).
* The goal of this script is to load the Keils's object file to the
* GR55xx RAM
* assuring that the GR55xx has been previously cleaned up.
*****************************************************************
*/
// Debugger reset(check Keil debugger settings)
// Preselected reset type(found in Options->Debug->Settings)is
// Normal(0);
// -Normal:Reset core & peripherals via SYSRESETREQ & VECTRESET bit
// RESET
// Load object file
LOAD %L
// Load stack pointer
SP = _RDWORD(0x00000000)
// Load program counter
$ = _RDWORD(0x00000004)
// Write 0 to vector table register, remap vector
_WDWORD(0xE000ED08, 0x00000000)
```

Note:

Keil supports executing debugger commands set by developers in the following order:

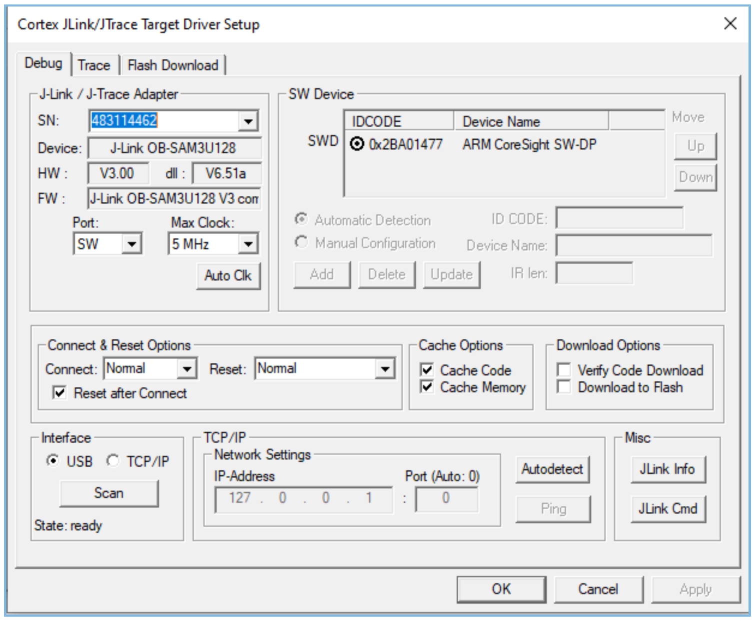
1. When **Options for Target 'GRxx_Soc'** > **Debug** > **Load Application at Startup** is enabled, the debugger first loads the file under **Options for Target 'GRxx_Soc'** > **Output** > **Name of Executable**.
2. Execute the command in the file specified in **Options for Target 'GRxx_Soc'** > **Debug** > **Initialization File**.
3. When options under **Options for Target 'GRxx_Soc'** > **Debug** > **Restore Debug Session Settings** are checked, restore corresponding Breakpoints, Watch Windows, Memory Display, and other settings.
4. When **Options for Target 'GRxx_Soc'** > **Debug** > **Run to main()** is checked, or the command `g,main` is discovered in **Initialization File**, the debugger automatically starts executing CPU commands, until running to the main() function.

4.6.2 Starting Debugging

After completing debugger configuration, click (**Start/Stop Debug Session**) on the Keil toolbar, to start debugging.

Note:

Make sure that both options under **Connect & Reset Options** are set to **Normal**, as shown in Figure 4-17. This is to ensure when you click **Reset** on the Keil toolbar after enabling **Debug Session**, the program can run normally.



J-Link / J-Trace Adapter
SN: 483114462
Device: J-Link OB-SAM3U128
HW : V3.00 dll : V6.51a
FW : J-Link OB-SAM3U128 V3 com
Port: SW
Max Clock: 5 MHz
Auto Clk

SW Device

	IDCODE	Device Name
SWD	0x2BA01477	ARM CoreSight SW-DP

Move Up Down
Automatic Detection
Manual Configuration
ID CODE:
Device Name:
IR len:
Add Delete Update

Connect & Reset Options
Connect: Normal
Reset: Normal
☑ Reset after Connect

Cache Options
☑ Cache Code
☑ Cache Memory

Download Options
☐ Verify Code Download
☐ Download to Flash

Interface
[✓ USB] TCP/IP
Scan
State: ready

TCP/IP
Network Settings
IP-Address: 127 . 0 . 0 . 1
Port (Auto: 0): 0
Autodetect
Ping

Misc
JLink Info
JLink Cmd

Figure 4-17 Setting **Connect** and **Reset** to **Normal** in **Connect & Reset Options**

4.6.3 Outputting Debug Logs

GR5525 SDK provides an APP LOG module and supports outputting debug logs of applications from hardware ports based on customization. Hardware ports include UART, J-Link RTT, and ARM Instrumentation Trace Macrocell (ARM

ITM). To use the APP LOG module, enable APP_LOG_ENABLE in *custom_config.h*, and configure APP_LOG_PORT based on the output method as needed.

4.6.3.1 Module Initialization

After configuration, you need to call app_log_init() during peripheral initialization to initialize the APP LOG module, including setting log parameters, and registering log output APIs and flush APIs.

The APP LOG module supports using `printf()` (a C standard library function) and APP LOG APIs to output debug logs. If you choose APP LOG APIs, you can optimize logs by setting log level, log format, filter type, or other parameters; if you choose `printf()`, set log parameters as "NULL".

Call the initialization function of corresponding module (refer to `SDK_Folder\platform\boards\board_SK.h` for details) and register corresponding transmission and flush APIs (see bsp_log_init() for reference) according to the configured output port. If UART is the output port, bsp_log_init() is implemented as follows:

```
void bsp_log_init(void)
{
#if APP_LOG_ENABLE

#if (APP_LOG_PORT == 0)
    bsp_uart_init();
#elif (APP_LOG_PORT == 1)
    SEGGER_RTT_ConfigUpBuffer(0, NULL, NULL, 0, SEGGER_RTT_MODE_BLOCK_IF_FIFO_FULL);
#endif

#if (APP_LOG_PORT <= 2)
    app_log_init_t   log_init;

    log_init.filter.level                 = APP_LOG_LVL_DEBUG;
    log_init.fmt_set[APP_LOG_LVL_ERROR]   = APP_LOG_FMT_ALL & (~APP_LOG_FMT_TAG);
    log_init.fmt_set[APP_LOG_LVL_WARNING] = APP_LOG_FMT_LVL;
    log_init.fmt_set[APP_LOG_LVL_INFO]    = APP_LOG_FMT_LVL;
    log_init.fmt_set[APP_LOG_LVL_DEBUG]   = APP_LOG_FMT_LVL;

#if (APP_LOG_PORT == 0)
    app_log_init(&log_init, bsp_uart_send, bsp_uart_flush);
#elif (APP_LOG_PORT == 1)
    app_log_init(&log_init, bsp_segger_rtt_send, NULL);
#elif (APP_LOG_PORT == 2)
    app_log_init(&log_init, bsp_itm_send, NULL);
#endif

#endif
    app_assert_init();
#endif
}
```

Note:

- The input parameters of app_log_init() include the log initialization parameter, log output API, and flush API (optional for registration).
- GR5525 SDK provides an APP LOG STORE module, which supports storing the debug logs in Flash and outputting the logs from Flash. To use the APP LOG STORE module, users need to enable APP_LOG_STORE_ENABLE in *custom_config.h*. This module is configured in the ble_app_rscs project (in `SDK_Folder\projects\ble\ble_peripheral\ble_app_rscs`). This configuration can be a reference when the APP LOG STORE module is used.
- Application logs output by using `printf()` cannot be stored by the APP LOG STORE module.

When debug logs are output through UART, the implemented log output API and flush API are bsp_uart_send() and bsp_uart_flush() respectively.

- bsp_uart_send() is the basis for two log output APIs: app_uart asynchronization (app_uart_transmit_async) and hal_uart synchronization (hal_uart_transmit). Users can choose the output methods as needed.
- bsp_uart_flush() is used to output the log data that is cached in memory in interrupt mode.

Note:

You can rewrite the above two APIs.

When debug logs are output through J-Link RTT or ARM ITM, the implemented log output API is bsp_segger_rtt_send() or bsp_itm_send(). No flush API is to be implemented in the two modes.

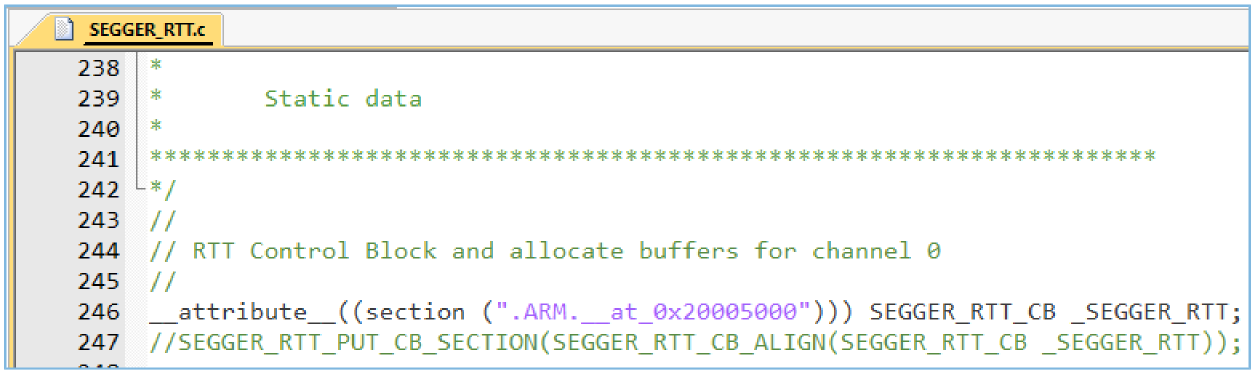
4.6.3.2 Application

After completing initialization of the APP LOG module, you can use any of the following four APIs to output debug logs:

- APP_LOG_ERROR()
- APP_LOG_WARNING()
- APP_LOG_INFO()
- APP_LOG_DEBUG()

In interrupt output mode, call app_log_flush() to output all the debug logs cached, to ensure that all debug logs are output before the SoC is reset or the system enters the sleep mode.

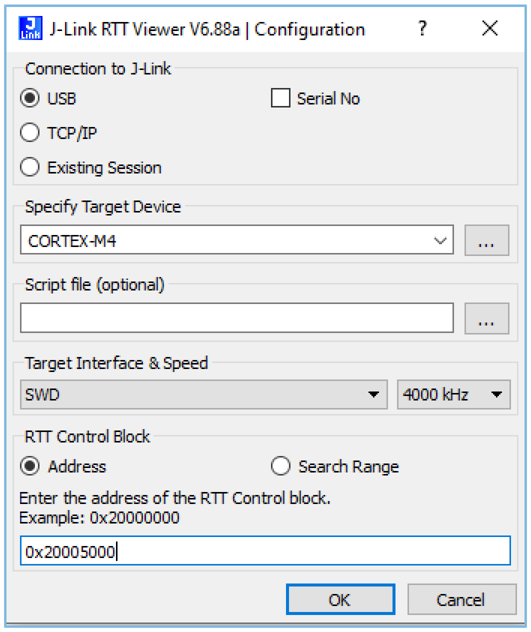
If you choose armcc for compilation and output logs through J-Link RTT, it is recommended to make the following modifications in *SEGGER_RTT.c*:



```
*
*       Static data
*
**********************************************************************
*/
//
// RTT Control Block and allocate buffers for channel 0
//
__attribute__((section (".ARM.__at_0x20005000"))) SEGGER_RTT_CB _SEGGER_RTT;
//SEGGER_RTT_PUT_CB_SECTION(SEGGER_RTT_CB_ALIGN(SEGGER_RTT_CB _SEGGER_RTT));
```

Figure 4-18 Creating RTT Control Block and placing it at 0x20005000

The figure below shows the reference configurations for J-Link RTT Viewer.



[● USB] ☐ Serial No

○ TCP/IP

○ Existing Session

CORTEX-M4

SWD 4000 kHz

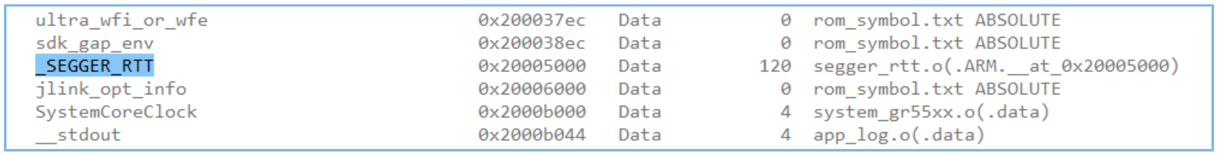
[● Address] ○ Search Range

Enter the address of the RTT Control block.
Example: 0x20000000

0x20005000

Figure 4-19 Configurations in J-Link RTT Viewer

The address of **RTT Control Block** can be specified by clicking **Address** and then entering a custom value; the input value can be set to the address of the **_SEGGER_RTT** structure in the .map file generated by the compiled project, as shown in the figure below. If creating RTT Control Block through the method recommended in Figure 4-18 and placing it at 0x20005000, you need to set **Address** to **0x20005000**.



```
ultra_wfi_or_wfe                         0x200037ec   Data           0  rom_symbol.txt ABSOLUTE
sdk_gap_env                              0x200038ec   Data           0  rom_symbol.txt ABSOLUTE
_SEGGER_RTT                              0x20005000   Data         120  segger_rtt.o(.ARM.__at_0x20005000)
jlink_opt_info                           0x20006000   Data           0  rom_symbol.txt ABSOLUTE
SystemCoreClock                          0x2000b000   Data           4  system_gr55xx.o(.data)
__stdout                                 0x2000b044   Data           4  app_log.o(.data)
```

Figure 4-20 Obtaining RTT Control Block address

Note:

If you choose GCC for compilation, modifications shown in Figure 4-18 is not required. The address to be entered for RTT Control Block in J-Link RTT Viewer should be the address of **_SEGGER_RTT** in the .map file generated by the compilation project.

4.6.4 Debugging with GRToolbox

GR5525 SDK provides an Android App, GRToolbox, to debug GR5525 Bluetooth LE applications. GRToolbox features the following:

- General Bluetooth LE scanning and connecting; characteristics read/write
- Demos for standard profiles, including Heart Rate and Blood Pressure
- Goodix-customized applications

Tip:

GRToolbox installation file is in `SDK_Folder\tools\GRToolbox\GRToolbox-Version.apk`.

5 Glossary

Table 5-1 Glossary

Name	Description
API	Application Programming Interface
ATT	Attribute Protocol
Bluetooth LE	Bluetooth Low Energy
DAP	Debug Access Port
DFU	Device Firmware Update
GAP	Generic Access Profile
GATT	Generic Attribute Profile
GFSK	Gaussian Frequency Shift Keying
HAL	Hardware Abstract Layer
HCI	Host Controller Interface
IoT	Internet of Things
L2CAP	Logical Link Control and Adaptation Protocol
LL	Link Layer
NVDS	Non-volatile Data Storage
OTA	Over The Air
PMU	Power Management Unit
PHY	Physical Layer
RF	Radio Frequency
SCA	System Configuration Area
SDK	Software Development Kit
SM	Security Manager
SoC	System-on-Chip
UART	Universal Asynchronous Receiver/Transmitter
XIP	Execute in Place